(An Autonomous Institution Affiliated to Anna University, Chennai) (Approved by AICTE, New Delhi, Accredited by NAAC with 'A' Grade), COIMBATORE 641 032

M.E. APPLIED ELECTRONICS



Curriculum & Syllabus 2018-2019

VISION AND MISSION OF THE INSTITUTION

VISION

To become a premier institution by producing professionals with strong technical knowledge, innovative research skills and high ethical values.

MISSION

IM1: To provide academic excellence in technical education through novel teaching methods.

IM2: To empower students with creative skills and leadership qualities.

IM3: To produce dedicated professionals with social responsibility.

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VISION AND MISSION OF THE DEPARTMENT

VISION

To become a Centre of Excellence in Electrical and Electronics Engineering, in every facet of Engineering Education.

MISSION

- M1. Provide a solid foundation in basic science, mathematics and engineering fundamentals enhancing the student's capability to identify, formulate, analyze and develop solutions for Engineering problems.
- M2. Create an ambiance for the students to develop and flourish their technical skills, design knowledge and innovative ideas to address the environmental issues and sustainable development of the society.
- M3. Inculcate moral values and leadership qualities to meet the challenges of life with courage and confidence.

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PROGRAM OUTCOMES (POs)

Engineering Graduates will be able to:

- PO 1. **Engineering knowledge**: Apply the knowledge of mathematics, science, engineering fundamentals, and an engineering specialization to the solution of complex engineering problems.
- PO 2. **Problem analysis**: Identify, formulate, review research literature, and analyze complex engineering problems reaching substantiated conclusions using first principles of mathematics, natural sciences, and engineering sciences.
- PO 3. **Design/development of solutions**: Design solutions for complex engineering problems and design system components or processes that meet the specified needs with appropriate consideration for the public health and safety, and the cultural, societal, and environmental considerations.
- PO 4. Conduct investigations of complex problems: Use research-based knowledge and research methods including design of experiments, analysis and interpretation of data, and synthesis of the information to provide valid conclusions.
- PO 5. **Modern tool usage**: Create, select, and apply appropriate techniques, resources, and modern engineering and IT tools including prediction and modeling to complex engineering activities with an understanding of the

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limitations.

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- PO 6. The engineer and society: Apply reasoning informed by the contextual knowledge to assess societal, health, safety, legal and cultural issues and the consequent responsibilities relevant to the professional engineering practice.
- PO 7. **Environment and sustainability**: Understand the impact of the professional engineering solutions in societal and environmental contexts, and demonstrate the knowledge of, and need for sustainable development.
- PO 8. **Ethics**: Apply ethical principles and commit to professional ethics and responsibilities and norms of the engineering practice.
- PO 9. **Individual and team work**: Function effectively as an individual, and as a member or leader in diverse teams, and in multidisciplinary settings.
- PO10. Communication: Communicate effectively on complex engineering activities with the engineering community and with society at large, such as, being able to comprehend and write effective reports and design documentation, make effective presentations, and give and receive clear instructions.
- PO11.**Project management and finance:** Demonstrate knowledge and understanding of the engineering and management principles and apply these to one's own work, as a member and leader in a team, to manage projects and in multidisciplinary environments.

PO12.Life-long learning: Recognize the need for, and have the preparation and ability to engage in independent and life-long learning in the broadest context of technological change.

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PROGRAM SPECIFIC OUTCOMES (PSOs)

- PSO 1. To analyze, design and implement solutions for simple and complex engineering problems that are economically feasible, eco-friendly and socially acceptable solutions in the field of Applied Electronics.
- PSO 2. To apply research and project management skills in Applied Electronics domain concerned with communication system by employing recent technologies.

PROGRAM EDUCATIONAL OBJECTIVES (PEOs)

- PEO 1. To enable graduates to develop solutions to real world problems in the frontier areas of Applied Electronics.
- PEO 2. To enable the graduates to adapt to the latest trends in technology through self-learning and to pursue research to meet out the demands in industries and Academia.
- PEO 3. To enable the graduates to exhibit leadership skills and enhance their abilities through lifelong learning.

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DETAILS OF CHANGES CARRIED OUT IN CURRICULUM & SYLLABUS

CBCS PATTERN

POSTGRADUATE PROGRAMMES

M.E. APPLIED ELECTRONICS REGULATION 2016

For the students admitted during the academic year 2018-2019 and onwards

SEMESTER I

S.No.	CourseCode	Course Title		Т	P	C	CIA	ESE	TOTAL	
	THEORY									
1	16MA1121	Advanced Applied Mathematics	3	1	0	4	40	60	100	
2	16AP1201	Embedded Systems	3	0	0	3	40	60	100	
3	16AP1202	Advanced Digital Logic System Design	3	1	0	4	40	60	100	
4	16AP1203	Advanced Microprocessor and Microcontroller	3	1	0	4	40	60	100	
5	16AP13XX	Professional Elective I	3	0	0	3	40	60	100	
6	16AP13XX	Professional Elective II	3	0	0	3	40	60	100	
PRACTICAL										
7	16AP1001	VLSI Design Laboratory	0	0	4	2	50	50	100	
		Total Credits:	18	3	4	23	290	410	700	

SEMESTER II

S.No.	Course Code	Course Title	L	Т	P	С	CIA	ESE	TOTAL	
1	16AP2201	Analysis and Design of Analog IntegratedCircuits	3	1	0	4	40	60	100	
2	16AP2202	ASIC and FPGA Design	3	1	0	4	40	60	100	
3	16AP2203	Advanced Digital Signal Processing	3	1	0	4	40	60	100	
4	16AP2204	Electromagnetic Interference and Compatibility	3	0	0	3	40	60	100	
5	16AP23XX	Professional Elective III	3	0	0	3	40	60	100	
6	16AP23XX	Professional Elective IV	3	0	0	3	40	60	100	
	PRACTICAL									
7	16AP2001	Embedded Systems Laboratory	0	0	4	2	50	50	100	
	Total Credits: 18 3 4 23 290 410 700									



For the students admitted during the academic year 2017-2018 and onwards SEMESTER III

S.No.	Course Code	Course Title		Т	P	С	CIA	ESE	TOTAL		
	THEORY										
1	16AP3201	Computer Architecture and Parallel Processing	3	0	0	3	40	60	100		
2	16AP33XX	Professional Elective V	3	0	0	3	40	60	100		
3	16AP33XX	Professional Elective VI	3	0	0	3	40	60	100		
	PRACTICAL										
4	16AP3001	Electronics System Design Laboratory	0	0	4	2	50	50	100		
5	16AP3901	Project Phase – I	0	0	12	6	50	50	100		
	Total Credits:			0	16	17	220	280	500		

SEMESTER IV

				_	_				
S.No.	Course Code	Course Title	L	T	P	C	CIA	ESE	TOTAL
		PRACT	CAL						5
1	16AP4902	Project Phase - II	0	0	24	12	100	100	200
		Total Credits:	0	0	24	12	100	100	200

Total No of Credits: 75

LIST OF PROFESSIONAL ELECTIVES

PROFESSIONAL ELECTIVE I

S.No.	Course Code	Course Title		T	P	C	CIA	ESE	TOTAL	
	THEORY									
1	16AP1301	Advanced Digital Image Processing	3	0	0	3	40	60	100	
2	16AP1302	Wireless Mobile Communication	3	0	0	3	40	60	100	
3	16AP1303	Intelligent Control and Its Applications	3	0	0	3	40	60	100	
4	16AP1304	Digital Control Engineering	3	0	0	3	40	60	100	
5	16AP1305	DSP Integrated Circuits	3	0	0	3	40	60	100	

PROFESSIONAL ELECTIVE II

S.No.	Course Code	Course Title	L	T	P	С	CIA	ESE	TOTAL
	1	THEORY							
1	16AP1306	CAD for VLSI Circuits	3	0	0	3	40	60	100
2	16AP1307	Multicore Architectures	3	0	0	3	40	60	100
3	16AP1308	Quantum Electronics	3	0	0	3	40	60	100
4	16AP1309	Sensors and Signal Conditioning	3	0	0	3	40	60	100
5	16AP1310	Semiconductor Memory Design & Testing	3	0	0	3	40	60	100



PROFESSIONAL ELECTIVE III

S.No.	CourseCode	Course Title	L	Т	P	C	CIA	ESE	TOTAL
		THEORY							
1	16AP2301	VLSI Design Techniques	3	0	0	3	40	60	100
2	16AP2302	Embedded Networking	3	0	0	3	40	60	100
3	16AP2303	Fiber Optic Sensors	3	0	0	3	40	60	100
4	16AP2304	Neural Networks and Its Applications	3	0	0	3	40	60	100
5	16AP2305	Medical Imaging Techniques	3	0	0	3	40	60	100

PROFESSIONAL ELECTIVE IV

S.No.	Course Code	Course Title		Т	P	С	CIA	ESE	TOTAL		
	THEORY										
1	16AP2306	Low Power VLSI Design	3	0	0	3	40	60	100		
2	16AP2307	Research Methodology	3	0	0	3	40	60	100		
3	16AP2308	Solid State Device Modeling and Simulation	3	0	0	3	40	60	100		
4	16AP2309	High Performance Networks	3	0	0	3	40	60	100		
5	16AP2310	Industrial Automation & Control	3	0	0	3	40	60	100		

PROFESSIONAL ELECTIVE V

S.No.	Course Code	Course Title		Т	P	С	CIA	ESE	TOTAL		
THEORY											
1	16AP3301	Testing of VLSI Circuits	3	0	0	3	40	60	100		
2	16AP3302	Photonics	3	0	0	3	40	60	100		
3	16AP3303	Nano Electronics	3	0	0	3	40	60	100		
4	16AP3304	Internetworking and Multimedia	3	0	0	3	40	60	100		
5	16AP3305	ASIC Design	3	0	0	3	40	60	100		

PROFESSIONAL ELECTIVE VI

S.No.	Course Code	Course Title	L	Т	P	С	CIA	ESE	TOTAL			
	THEORY											
1	16AP3306	Robotics	3	0	0	3	40	60	100			
2	16AP3307	MEMS and NEMS	3	0	0	3	40	60	100			
3	16AP3308	System on Chip Design	3	0	0	3	40	60	100			
4	16AP3309	Wireless Adhoc and Sensor Networks	3	0	0	3	40	60	100			
5	16AP3310	Applied Medical Image Processing	3	0	0	3	40	60	100			

CREDIT DISTRIBUTION

Semester	I	II	III	IV	TOTAL
Credits	23	23	17	12	75

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SEMESTER I

PROGRAMME	COURSE COD	NAME OF THE COURSE	L	T	P	C
M.E.	16MA1121	ADVANCED APPLIED MATHEMATICS	3	1	0	4
Course Objective	 Formulate a situation. Understand Develop the problems re 	g of hypothesis to infer outcome of experiments. Independent of a linear property of the prope	roject activ	vities.		

Unit	Description	Instructional hours
I	TESTING OF HYPOTHESES	
	Sampling distributions -Type I and Type II errors - Tests based on Normal, t, Chi-Square and F distributions for testing of mean, variance and proportions -Tests for Independence of	12
TT	attributes and Goodness of fit.	
II	LINEAR PROGRAMMING Formulation - Graphical solution - Simplex method - Artificial variable Techniques - Transportation and Assignment Models	12
III	SCHEDULING BY PERT AND CPM	
	Network Construction - Critical Path Method - Project Evaluation and Review technique -	12
	Resource Analysis in Network Scheduling.	
IV	LINEAR ALGEBRA	
	Vector spaces – norms - Inner Products - Eigen values using QR Factorization - generalized eigenvectors - Canonical forms - singular value decomposition and applications -pseudo inverse - least square approximations -Toeplitz matrices and some applications.	12
V	FUZZY LOGIC AND FUZZY ALGEBRA	12
	Basic principles of Fuzzy logic - Fuzzy sets of operations - Fuzzy membership Matrix.	12
	Total Instructional Hours	60
		1.1

CO1: Acquire the basic concepts of Statistical techniques for solving mathematical problems which will be useful in solving engineering problems.

CO2: Apply transportation and assignment models to find optimal solution in warehousing and travelling. Prepare project scheduling using PERT and CPM.

Course Outcome

CO3: Achieve an understanding of the basic concepts of algebraic equations and method of solving

CO4: Analysis the linear algerbra QR factorization.

CO5: Apply the Fuzzy logic in power system problems.

TEXT BOOKS:

- T1. Richard Bronson, Gabriel B.Costa, "Linear Algebra", Academic Press, Second Edition, 2007.
- T2. Richard Johnson., "Miller & Freund's Probability and Statistics for Engineer", Prentice Hall, Seventh Edition, 2007
- T3. Taha H.A., "Operations Research: An Introduction", 8th Edition, Pearson Education, 2008.

REFERENCE BOOKS:

- R1. Gupta S.C. and Kapoor V.K. "Fundamentals of Mathematical Statistics", Sultan an Sons, 2001.
- R2. Prem Kumar Gupta, D.S. Hira, "Operations Research", S.Chand & Company Ltd, New Delhi, 3rd Edition, 2008.
- R3. Paneer Selvam, 'Operations Research', Prentice Hall of India, 2002.

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	C
M.E.	16AP1201	EMBEDDED SYSTEMS	3	0	0	3
	d awareness about Hard	ware and software design aarchitecture	for embe	dded P	rocesso	rs

with real time examples.

Course

- 2. Learn various techniques of embedded system design.
- Objective 3. Gain various types of networking and hardware structures.
 - Study system design for embedded Processor.
 Trouble shoot certain modern embedded systems.

Unit	Description	Instructional hours
I	INTRODUCTION Embedded Computers, Characteristics of Embedded Computing Applications, Challenges in Embedded Computing system Design, Embedded system design requirements process, Specification, Architectural Design, Designing Hardware and Software Components, System Integration, Formalism for System Design, Structural Description, Behavioral Description, Design Example: Model Train Controller, ARM processor and memory organization.	9
II	EMBEDDED PROCESSORS SHARC processor Memory organization, Data operations, Flow of Control, parallelism with instructions, CPU Bus configuration, ARM Bus, SHARC Bus, Memory devices, Input/output devices, Component interfacing and debugging, designing with microprocessor development Design Example: Alarm Clock. Hybrid Architecture	9
III	DISTRIBUTED EMBEDDED ARCHITECTURE Hardware and Software Architectures, Networks for embedded systems- I2C, CAN Bus, SHARC link supports, Ethernet, Myrinet, Internet, Network-Based design Communication Analysis, system performance Analysis, Hardware platform design, Allocation and scheduling, Design Example: Elevator Controller.	9
IV	REAL-TIME CHARACTERISTICS Clock driven Approach, weighted round robin Approach, Priority driven Approach, Dynamic Versus Static systems, effective release times and deadlines, Optimality of the Earliest deadline first (EDF)algorithm, challenges in validating timing constraints in priority driven systems, Off-line Versus On-line scheduling.	9
V	SYSTEM DESIGN TECHNIQUES Design Methodologies, Requirement Analysis, Specification, System Analysis and Architecture Design, Quality Assurance, Design Example: Telephone PBX System Architecture, Ink jet printer Hardware Design and Software Design, Personal Digital Assistants, Set-top Boxes.	9
	Total instructional hours	45
Course Outcome	CO3: Design more advanced Embedded based system	

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TEXT BOOKS:

- T1. Wayne Wolf, "Computers as Components: Principles of Embedded Computing System Design", Morgan Kaufman Publishers, 2008.
- T2. Jane.W.S. Liu, "Real-Time systems", Pearson Education Asia, 2000.

REFERENCE BOOKS:

- C. M. Krishna and K. G. Shin, "Real-Time Systems", McGraw-Hill, 1997 R1.
- R2. Frank Vahid and Tony Givargis, "Embedded System Design: A Unified Hardware / Software Introduction", John Wiley & Sons, 2006.







PROG	GRAMME	COURSE CODE	NAME OF THE COURSE	L	T	P	C
,]	M.E.	16AP1202	ADVANCED DIGITAL LOGIC SYSTEM DESIGN	3	1	0	4
-	Course ojective	 Study the concepts Apply the concept Learn the concept 	Asynchronous Sequential Circuit Design. s of programmable logic devices. ts of System Design Using VHDL and Pros of fault modeling and fault - tolerant system of field programmable gate array.		Devices.		
Unit			Description			tructio hours	
I	Designing Mealy Mac		nsing multiplexer, decoder – Finite State State Diagram – State table.	Machines -	=	12	
III	Basic conc Programma Logic Arch circuits usin of state made	cepts — Programming tec able Array Logic (PLA) aitectures — 16L8 — 16R ng PLDs — Complex PL	hnologies - Programmable Logic Elemen - Programmable Array Logic (PAL) — Pro 4 — 22V10 — Design of combinational a Ds (CPLDs) –Xilinx cool runner architect c State Machines (ASM) chart as a design	ogrammable nd sequentia ture - Design		12	
111	Types of F. Blocks (CL	PGA - Xilinx XC3000	series - Logic Cell Array (LCA) – Config ks (IOB) - Programmable Interconnection			12	,
IV V	Hardware Entities and - Selected delays - F Packages a	d Architectures – Concu signal assignment – C Behavioral, Data flow nd Libraries – IEEE 116	VHDL: Data Objects - Data types rrent signal assignment - Conditional sign concurrent statements - Sequential state and Structural modeling - Attributes 4 std logic - Subprograms: Functions and LT - TOLERANT SYSTEMS	nal assignmer ments —Deli — Generics	nt ta	12	
y	Defects, er Logic circu sequential Built in Se	rors, faults, Levels of I nits: Path sensitization r logic circuit, Design fo If Test. Fault avoidance	Fault models, Types, Fault Detection in method, Boolean difference method. Fault Testability: Scan path Testing, Boundard fault - tolerance - Techniques of fau	It Detection i ary Scan Tes	in st,	12	
	Hardware I	fault - tolerance: Static a	nd Dynamic	-4:1 TT		60	

CO1: Design and analysis of asynchronous sequential circuit.

Course Outcome CO2: Learn of programmable logic devices.

CO3: Design and carry out of field programmable gate array.

CO4: Explore fault diagnosis and testability algorithm.

CO5: Design and analysis of hardware description languages.

TEXT BOOKS:

T1. Fundamental of Digital logic design with VHDL-Second edition Stephen Brown/ Zvonko

Digital logic design -Brain Holdsworth and Clive Woods. IV Edition T2.

REFERENCE BOOKS:

Charles H Roth and Lizy Kurian John "Digital Systems Design Using VHDL," Cengage R1. Learning,2013.

R2. Bhaskar J., "A VHDL Primer", Prentice Hall of India learinng, 2012.

60

Total Instructional Hours

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	L	T	P	\mathbf{C}
M.E.	16AP1203	ADVANCED MICROPROCESSOR AND MICROCONTROLLER	3	1	0	4
Course Objective	microcontrollers. 2. Impart the basic k 3. Express the basic k 4. Apply the ARM p	nre and programming of advanced Intel microprocessors about the Pentium Processors. Knowledge about the Arm Processors. Frocessors in real time development. Inicrocontrollers PIC.	essors a	and		

Unit	Description	Instructional hours
I	MICROPROCESSORS - OVERVIEW Generic Architecture – Instruction Set – Data formats – Addressing modes – Memory hierarchy – Register file – Cache – Virtual memory and paging – Segmentation – Pipelining – The Instruction Pipeline – Pipeline hazards – Instruction level parallelism – Reduced instruction set – Computer principles – RISC versus CISC.	12
П	HIGH PERFORMANCE CISC ARCHITECTURE – PENTIUM CPU Hardware Architecture - Bus Operations – Pipelining – Brach predication – Floating point unit – Operating Modes – Paging – Multitasking – Exception and Interrupts – Instruction set – addressing modes – Programming the Pentium processor (Decimal to Binary and Binary to Decimal).	12
III	HIGH PERFORMANCE RISC ARCHITECTURE – ARM Organization of CPU – Bus architecture – Memory management unit - ARM instruction set – Thumb Instruction set - addressing modes – Programming the ARM processor (Using Thump Instruction Set).	12
IV	ARM APPLICATION DEVELOPMENT FIR filter – IIR filter – Discrete Fourier transform – Exception handling – Interrupts – Interrupt handling schemes- Firmware and boot loader – Embedded Operating systems – Peripheral Interface – Application of ARM Processor – Caches – Memory protection Units – Memory Management units	12
V	PIC MICROCONTROLLER CPU Architecture – Instruction set – interrupts – Timers – I/O port Expansion - I ² C Interfacing – UART - A/D Converter. Total instructional hours	12 60
Course Outcome	CO1: Learn the fundamentals and architecture of microprocessors. CO2: Illustrate the Pentium architectures and programming. CO3: Describe the ARM architectures and programming. CO4: Develop the ARM processor for real time applications. CO5: Design the basics of PIC microcontroller with programming knowledge.	

TEXT BOOKS:

- T1. Daniel Tabak, "Advanced Microprocessors", McGraw Hill.Inc., 1995.
- T2. James L. Antonakos, "The Pentium Microprocessor" Pearson Education, 1997.

REFERENCE BOOKS:

- R1. Steve Furber, "ARM System On Chip architecture", Addision Wesley, 2000.
- R2. Andrew N.Sloss, Dominic Symes and Chris Wright "ARM System Developer's Guide: Designing and Optimizing System Software", First edition, Morgan Kaufmann Publishers, 2004.
- R3 John. B. Peatman, "Design with PIC Microcontroller", Prentice hall, 1997.

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Programme	COURSE CODE	NAME OF THE COURSE	L	T	P	\mathbf{C}
M.E.	16AP1001	VLSI DESIGN LABORATORY	0	0	4	2
Course Objective	 Study various Gain the know Analyze vario 	ftware tools for VLSI. design methods for VLSI circuits. vledge about circuit designing. sus controllers and its real time Appl mplementation of System using ASI				

Expt. No.	Description of the experiments
1.	Design and Simulation of Arithmetic /logic operator circuits using verilog/VHDL
2.	Modeling of Combinational/Sequential Circuits Using Verilog /VHDL
3.	Simulation of schematic /RTL using Xilinx ISE Tool
4.	Design and Implementation of ALU in FPGA using VHDL and Verilog
5.	System design using ASIC
6.	Modeling of Sequential Digital system using Verilog and VHDL
7.	Modeling of MAC unit using verilog / VHDL
8.	Modeling of ALU using verilog / VHDL
9.	Design and 8-bit signed multiplication algorithm using verilog / VHDL
10.	Design and technological mapping of RTL net list in Xillinx ISE Tool
	Total practical hours 45

CO1: Use the software tools for designing and simulation.

Course Outcome

CO2: Design the various VLSI circuits using VHDL programming..
CO3: Analyse anddesign the Implementation of ALU in FPGA using VHDL and Verilog

CO4: Analysis the MAC unit using verilog.
CO5: Design the VLSI circuits using Xillinx ISE tool.

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SEMESTER II

PROGRAMME	COURSE CODE	NAME OF THE COURSE ANALYSIS AND DESIGN OF	L	T	P	C
M.E.	16AP2201	ANALOG INTEGRATED CIRCUITS	3	1	0	4

1. Design the single stage amplifiers using pmos and nmos driver circuits with different loads.

2. Analyze high frequency concepts of single stage amplifiers and noise characteristics associated with differential amplifiers.

Course Objective 3. Study the different types of current mirrors and to know the concepts of voltage and current reference circuits.

4. Gain the various applications in operational amplifier.

5. Learn the different concepts in stability and frequency compensation.

Unit	Description	Instructional hours
Ι	SINGLE STAGE AMPLIFIERS Common source stage, Source follower, Common gate stage, Cascade stage, Single ended and differential operation, Basic differential pair, Differential pair with MOS loads	12
II	FREQUENCY RESPONSE AND NOISE ANALYSIS Miller effect, Association of poles with nodes, frequency response of common source stage. Source followers, Common gate stage, Cascade stage, Differential pair, Statistical	12
III	characteristics of noise, noise in single stage amplifiers, noise in differential amplifiers. OPERATIONAL AMPLIFIERS Concept of negative feedback, Effect of loading in feedback networks, operational amplifier performance parameters, One-stage Op Amps, Two-stage Op Amps, Input range limitations, Gain boosting, slew rate, power supply rejection, noise in Op Amps.	12
IV	STABILITY AND FREQUENCY COMPENSATION General considerations, Multipole systems, Phase Margin, Frequency Compensation, and Compensation of two stage Op Amps, Slewing in two stage Op Amps, and Other compensation techniques	12
V	BIASING CIRCUITS Basic current mirrors, cascade current mirrors, active current mirrors, voltage references, supply independent biasing, temperature independent references, PTAT current mirrors, voltage references, and the current mirrors active current mirrors, voltage references, supply independent biasing, temperature independent references, PTAT current mirrors.	
	generation, Constant-Gm Biasing Total instructional hours	s 60
-	CO1: Design and analysis of amplifiers. CO2: Aquire of frequency response and noise analysis. CO3: Familiarize the Operational Amplifiers. CO4: Compose different types of Biasing Circuits. CO5: Gain knowledge about the engineering applications of Analog Integrated Circuits.	ircuits.

- TEXT BOOKS:
 Paul R. Gray, Paul J. Hurst, Stephen H. Lewis, Robert G. Meyer, Analysis and Design of Integrated Circuits, 5th Edition, Wiley, 2009.
- T2. Behzad Razavi, "Design of Analog CMOS Integrated Circuits", Tata McGraw Hill, 2001.

REFERENCE BOOKS:

- R1. Willey M.C. Sansen, "Analog design essentials", Springer, 2006.
- R2. Grebene, "Bipolar and MOS Analog Integrated circuit design", John Wiley & sons, Inc., 2003.
- Phillip E.Allen, Douglas R. Holberg, "CMOS Analog Circuit Design", Second edition, Oxford University Press, 2002.

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	L	T	P	C
M.E.	16AP2202	ASIC AND FPGA DESIGN	3	1	0	4
Course Objective	 Analyze the synthesis, Familiarize the different 	of different types of ASIC. Simulation and testing of systems. It types of programming technologies a high performance algorithms and its app or and Synthesizer	nd logic	devices in A	es. SICs.	

Unit	**	Description	Instructional hours
I	Types of ASIC C cell - D Logical	DUCTION TO ASIC AND LIBRARY DESIGN of ASICs - Design flow - Case Study: SPARC Station 1 - Economies of ASICs - Cell Libraries - CMOS Transistors - Combinational Logic Cell - Sequential logic ata path logic cell - I/O Cells - Transistor Resistance and Parasitic Capacitance - effort - Library cell design - Library architecture.	12
II	Anti fu benchm Virtex I	RAMMABLE ASIC se -Static RAM - EPROM and EEPROM technology - Practical issues - PREP arks - Actel ACT - Xilinx LCA -Altera FLEX - Altera MAX - Xilinx Spartan - FPGAs - Altera Cyclone FPGAs	12
III	DC inp	RAMMABLE ASIC I/O uts and Outputs – Totem Pole output –AC inputs and Outputs – Clock input – input – Supply bounce – Noise Margin – Meta-stability - Case Study: Xilinx 0 IOB	12
IV	Actel A	RAMMABLE ASIC INTERCONNECT ACT 1/2/3 - Xilinx LCA - Xilinx EPLD - Altera MAX 5000/7000/9000 - Altera EPGAs - Case study: Spartan-3 Block RAM	12
V	 V LOGIC SIMULATION & SYNTHESIS Types of simulation – Logic systems – How logic Simulation works – Delay models – Limitations of Logic simulation – Static Timing analysis - Design Systems - Logic synthesis – EDIF – Schematic Entry – Inside a logic Synthesizer – Case Study: Comparator/MUX 		
		Total instructional hours	60
= ===	irse	CO1: Demonstrate advanced knowledge in programming techniques. CO2: Apply advanced simulation methods for design circuits. CO3: Gain knowledge about ASICs and implement in different applications.	

CO4: Impart the programming of ASIC Interconnect.
CO5: Compute the programming of ASIC using simulators.

TEXT BOOKS:
T1. M.J.S. Smith, "Application Specific Integrated Circuits", Addison -Wesley Longman Inc., 2004.
T2. Wayne Wolf, "FPGA-Based System Design", Prentice Hall PTR, 2004.

REFERENCE BOOKS:

R1. R.Rajsuman and Santa Clara, "System-on-a-Chip Design and Test", CA: Artech House Publishers, 2000.
R2. F.Nekoogar, "Timing Verification of Application-Specific Integrated Circuits (ASICs)", Prentice Hall PTR,

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	\mathbf{C}
M.E.	16AP2203	ADVANCED DIGITAL SIGNAL PROCESSING	3	1	0	4
Course Objective	Processing. 2. Analyze Power spe 3. Impart knowledge i 4. Apply wavelet tran	s course is to provide indepth treatment on method ctrum estimation and Random Signal Processing. in various types and working of Adaptive Filters. sforms. ations of sub band coding.	ls in disc	crete I)igital	I

Unit	Description	Instructional hours
Ι	PISCRETE RANDOM SIGNAL PROCESSING Random Process - Ensemble Averages - Gaussian Processes-Stationary Process - Auto covariance and auto correlation matrices - Ergodicity - Whitenoise - weiner Khitchine relation- Power spectral density -Spectral Factorization Theorem, Special typeof random process - Signal modeling-Least Squares method, Pade approximation.	12
II	SPECTRUM ESTIMATION Parametric estimation:Bias and consistency Non-Parametric methods —The Periodogram-Correlation method - Co-variance estimator - Performance analysis of various estimators — Unbiased consistent estimators - Periodogram estimator - Barlett spectrum estimation - Welch estimation Model based approach - AR, MA, ARMA Signal modeling -parameter estimation using Yule-Walker method	12
III IV	LINEAR ESTIMATION AND PREDICTION Maximum likelihood criterion - Efficiency of estimator - Least mean squared error criterion - Wiener filter -Forward and backward prediction, Solution of normal equations - Linear prediction, Prediction error - Whitening filter, Inverse filter - Levinson recursion, Lattice realization, Levinson recursion algorithm for solving Toeplitz system of equations. ADAPTIVE FILTERS	12
.,	Concepts of adaptive filters-FIR Adaptive filters - Newton's steepest descent method - Adaptive filters based on steepest descent method - Widrow Hoff LMS Adaptive algorithm - Adaptive channel equalization - Adaptive echo canceller - Adaptive noise cancellation - RLS Adaptive filters - Exponentially weighted RLS - Sliding window RLS - Simplified IIR LMS Adaptive filter.	12
V	MULTIRATE DIGITAL SIGNAL PROCESSING Mathematical description of change of sampling rate - Interpolation and Decimation - Continuous time model - Direct digital domain approach - Decimation by integer factor - Interpolation by an integer factor - Single and multistage realization - Poly phase realization - Applications to sub band coding - Wavelet transform and filter bank implementation of wavelet expansion of signals.	12
	Total instructional hours	60

CO1: Design adaptive filters for a given application.

Course Outcome CO2: Intend analysis of multirate DSP systems.

CO3: Familiarize and Design Adaptive Filters. CO4: Study and Solve toeplitz equation.

CO5: Apply and Design wavelet transforms in DSP.

TEXT BOOKS:

- Monson H. Hayes, "Statistical Digital Signal Processing and Modeling", John Wiley and Sons Inc., New York, 2006.
- John G. Proakis, Dimitris G. Manolakis, "Digital Signal Processing", Prentice Hall of India, New Delhi, 2005.

REFERENCE BOOKS:

- R1. Sophoncles J. Orfanidis, "Optimum Signal Processing", McGraw-Hill, 2000.
- R2. Simon Haykin, "Adaptive Filter Theory", Prentice Hall, Englehood Cliffs.

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PROGRAMME M.E.		COURSE CODE	NAME OF THE COURSE ELECTROMAGNETIC	L	T	P	C
		16AP2204	3	0	0	3	
Course Objective	1. 2. 3. 4. 5.	EMI/EMC Provide knowledge on Identify the various tec Design PCB resistant	fundamentals that are essential for electronary various EMI sources and victims. Chniques used in EMC (Electromagnetic of EMI ternational standards in EMI Measurement	ompatib		in the f	ield of
						¥	

Unit	Description	Instructional hours				
Ι	EMI/EMC CONCEPTS					
	EMI-EMC definitions and Units of parameters; Sources and victim of EMI; Conducted	9				
	and Radiated EMI Emission and Susceptibility; Transient EMI, ESD; Radiation Hazards.					
II	EMI COUPLING PRINCIPLES					
	Sources of Conducted, and radiated interference; Electromagnetic pulse; possible future					
	interference sources; Interference coupling by Conduction and Radiation. Common	9				
	ground impedance coupling; Common mode and ground loop coupling; Differential mode coupling; Power mains and Power supply coupling; Design practices employed to					
	minimize interference coupling					
III	EMI CONTROL TECHNIQUES					
	Shielding, Filtering, Grounding, Bonding, Isolation transformer, Transient suppressors,	9				
	opto isolators, Cable routing, Signal control					
IV	PCB DESIGN	9				
	Transmitter, Receiver, Antenna, Power Supply, Motors, Control devices, Digital Circuits,					
1210	Digital computer Integrated circuit sucessapility					
V	EMI MEASUREMENTS AND STANDARDS					
	Open area test site; TEM cell; EMI test shielded chamber and shielded ferrite lined					
	anechoic chamber; Tx /Rx Antennas, Working Principles of EMI sensing Device; EMI	9				
	Rx and spectrum analyzer; Civilian standards-CISPR, FCC, IEC, EN; Military standards-MIL461E/462.					
	Total instructional hours	45				
	Total listi uctional nouls	43				
	CO1: Real world EMC deign constraints and to achieve the most cost effective des all requirements.	ign that meets				
Cou	CO2: Diagnose and solve the basic electromagnetic compatibility problems.					
Outco	CO3: Designing the electronic system that function without errors or problems that	are related to				
Suite	electromagnetic compatibility.					
	CO4: Measuring the EMI with various methods and comparing it with standards.					

- T1. V.P.Kodali, "Engineering EMC Principles, Measurements and Technologies", IEEE Press, Newyork, 1996.
 T2. S.Sathyamurthy "Basics of Electromagnetic Compatibility "sams publishers, 2008.

CO5: Controlling techniques for EMI and EMC.

REFERENCE BOOKS:

- R1. Henry W.Ott., "Noise Reduction Techniques in Electronic Systems", A Wiley Inter Science, 1992.
 R2. Bemhard Keiser, "Principles of Electromagnetic Compatibility", 3rd Ed, Artech house, 2008.
- R3. C.R.Paul,"Introduction to Electromagnetic Compatibility", John Wiley and Sons, Inc, 1992.

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M.E.		16AP2001	EMBEDDED SYSTEMS LABORATORY	0	0	4	2
Cours Objecti	3	Study and design Design the Imple Design, simulatio	ARM processor and real time application wireless network using embedded systementation of ALU in FPGA using VHDI and analysis of signal integrity. In the controller and simulator.	ns.	ilog.		
Expt. No.			Description of the experiments				
1.	Study of 32	bit ARM7 microc	ontroller RTOS and its application				
2.	Testing RTOS environment and system programming						
3.	Designing of wireless network using embedded systems						
4.	Implement	ation of ARM with	FPGA				
5.	System des	sign using PIC micr	o controller-Train controller.				
6.	Elevator co	ontroller using PIC	Micro controller				
7.	Flash contr	roller programming	data flash with erase, verify and fusing				
8.	RTC using	PIC Micro control	ler.				
9.	Design, sin	nulation and analys	sis of signal integrity				
	3 ", """	•		Tota	l practi	cal hours	45

PROGRAMME COURSE CODE NAME OF THE COURSE L T P C



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SEMESTER III

PROGRAMME	COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	\mathbf{C}
M.E.	16AP3201	COMPUTER ARCHITECTURE AND PARALLEL PROCESSING	3	0	0	3
Course Objective	 Discriminate bety Infer memory tec Describe the perf 	Formance of various computer architectures. ween the various data processing architectures. chnology and measure its performances. Formance of various multiprocessor architectures. us multi core architectures.				

Unit	Description	Instructional Hours			
I	COMPUTER DESIGN AND PERFORMANCE MEASURES Concepts of Computer Design – Parallel and Scalable Architectures – Multiprocessors – Multivector and SIMD architectures - Multi threaded architectures – Data-flow architectures - Performance Measures.	9			
II	PARALLEL PROCESSING, PIPELINING AND ILP Instruction Level Parallelism and Its Exploitation - Concepts and Challenges - Overcoming Data Hazard with Dynamic Scheduling Dynamic Branch Prediction - Speculation - Multiple Issue Processors - Performance and Efficiency in Advanced Multiple Issue Processors.	9			
III	MEMORY HIERARCHY DESIGN Memory Hierarchy - Memory Technology and Optimizations - Cache memory - Optimizations of Cache Performance - Memory Protection and Virtual Memory - Design of Memory Hierarchies.				
IV	MULTIPROCESSOR Symmetric and distributed shared memory architectures —Cache coherence issues — Performance				
V	MULTI-CORE ARCHITECTURES Software and hardware multithreading – SMT and CMP architectures – Design issues –Case				
	Total Instructional Hours	45			
Cou outc	CO3: Design memories under various hierarchies.				

TEXT BOOKS:

- T1. Kai Hwang, "Advanced Computer Architecture", McGraw Hill International, 2001.
- T2. John L. Hennessey and David A. Patterson, "Computer Architecture A quantitative approach", Morgan Kaufmann / Elsevier, 4th Edition, 2007.

REFERENCE BOOKS:

- R1. David E. Culler, Jaswinder Pal Singh, "Parallel Computing Architecture: A hardware/ software Approach", Morgan Kaufmann / Elsevier, 1997.
- R2. John P. Shen, "Modern processor design. Fundamentals of super scalar processors", Tata McGraw Hill 2003.
- R3. William Stallings, "Computer Organization and Architecture Designing for Performance", Pearson Education, Seventh Edition, 2006.

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PROGRAM	ME COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	C		
M.E.	16AP3001	ELECTRONICS SYSTEM DESIGN LABORATORY	0	0	4	2		
Course Objective	Design system using 8086 a Study the different interface Intend and analysis of real ti	s using Embedded Microcontroller. ime signal processing system. d electronics system (Analog and Digital Sys		ferent	proces	is.		
Expt. No.	Description of the experiments							
1	System design using PIC, MSP430, '51 Microcontroller and 16- bit Microprocessor - 8086.							
2	Study of different interfaces (usin	ng Embedded Microcontroller).						
3	Implementation of Adaptive Filters and multistage multirate system in DSP Processor.							
4	Simulation of QMF using Simula	ation Packages.						
5	Analysis of Asynchronous and cl	locked synchronous sequential circuits.						
6	Built in self test and fault diagno	sis.						
7	Sensor design using simulation to	ools.						

Total Practical Hours

45

CO1: Design various analog / digital transceiver systems and control different process.

Course Outcome

Processing.

8

CO2: Write programs in Xilinx Microcontroller (8051) and DSP processor.

Design and analysis of real time signal processing system-Data acquisition and signal

CO3: Analyze Synchronous and Asynchronous sequential circuits.

CO4: Propose interfaces using embedded Microcontroller.

CO5: Design and analysis of real time signal processing system.

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PROGRAMME

COURSE CODE

NAME OF THE COURSE

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M.E.

16AP3901

PROJECT PHASE - I

6

1. Analyze a methodology to select a project and able to develop a hardware/software project.

Course

Transform the ideas behind the project with clarity.

Objective

Validate the technical report.

Description of the project work

A candidate is permitted to work on projects in an Industrial / Research Organization, on the recommendations of the Head of the Department concerned.

A project must be selected either from research literature published list or the students themselves may propose suitable topics in consultation with their guide.

The aim of the project work is to strengthen the comprehension of principles by applying them to a new problem which may be the design and manufacture of a device, a research investigation or a design problem.

The project work shall be supervised by a supervisor of the department, (and an expert in industry if it is a industrial project), and the student shall be instructed to meet the supervisor periodically and to attend the review committee meeting for evaluation of the progress.

In case of candidates not completing Phase-I of project work successfully, the candidates can undertake Phase-I again in the subsequent semester. In such cases the candidates can enroll for Phase-II, only after successful completion of Phase-I.

The Project report shall be prepared and submitted according to the approved guidelines as given by the Controller of Examination and bonafied duly signed by Supervisor and the Head of the Department.

CO1: Realize the skills acquired in the previous semesters to solve complex engineering problems.

CO2: Build up an innovative model / prototype of an idea related to the field of specialization.

Course Outcome CO3: Create the work individually to identify, troubleshoot and build products for environmental and societal issues.

CO4: Effective presentation of ideas with clarity.

CO5: Evaluate surveys towards developing a product which helps in life time learning.

SEMESTER IV

PROGRAMME	COURSE CODE	NAME OF THE COURSE	L	T	P	C
M.E.	16AP4902	PROJECT PHASE - II	0	0	24	12

1. Analyze a methodology to select a project and able to develop a hardware/software project.

Course

2. Transform the ideas behind the project with clarity.

Objective

3. Validate the technical report.

Description of the project work

The Project work (Phase II) shall be pursued for a minimum prescribed period as per regulation.

The project work shall be supervised by a supervisor of the department, (and an expert in industry if it is a industrial project), and the student shall be instructed to meet the supervisor periodically and to attend the review committee meeting for evaluation of the progress.

The Project report shall be prepared and submitted according to the approved guidelines as given by the Controller of Examination and bonafied duly signed by Supervisor and the Head of the Department.

CO1: Realize the skills acquired in the previous semesters to solve complex engineering problems.

CO2: Build up an innovative model / prototype of an idea related to the field of specialization.

Course Outcome CO3: Create the work individually to identify, troubleshoot and build products for environmental and societal issues.

CO4: Effective presentation of ideas with clarity.

CO5: Evaluate surveys towards developing a product which helps in life time learning.

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PROFESSIONAL ELECTIVE 1								
PROG	RAMME	(COURSE CODE	NAME OF THE COURSE	L	T	P	C
N	M.E. 16AP1301 ADVANCED DIGITAL IMAGE PROCESSING 3 0				0	0	3	
	Course Objective 1. Learn the image fundamentals and mathematical transforms necessary for im Study the image enhancement techniques. 2. Revise the image segmentation and representation techniques. 3. Independently design and carry out the basic knowledge in image Compress 4. Study the basic knowledge about Image Filtering And Restoration					C 1	essing.	
Unit	it Description				Instructional hours			
I DIGITAL IMAGE FUNDAMENTALS Elements of digital image processing system-Image sensing and acquisition- Image sampling and quantization – Basic relationship between Pixels					9			
	II IMAGE TRANSFORMS AND IMAGE ENHANCEMENT Need for image transforms- Discrete Wavelet transform- Harr Wavelets- Spatial domain methods- Frequency domain methods- Histogram modification techniques-median filtering- Low pass filtering- averaging of multiple images high pass filtering.						9)
	III IMAGE FILTERING AND RESTORATION Image observation models- restoration in the presence of noise only- spatial filtering: mean filters, order statistics filters, adaptive filters- Inverse filtering- Wiener filtering – Constrained least squares filtering- blind deconvolution.					ç)	
IV V	Edge det processing thresholdi Signature descriptor	tection tectio	on: Gradient oper ia Hough transfor adaptive threshold- bundary segments, s	ID REPRESENTATION ators-edge linking and boundary d m, Graph theoretic techniques-Thre Representation: Chain codes, Polygona skeletons-Boundary descriptors: Shape degional descriptors: Texture-Relational	sholding: l approxin numbers,	nations, Fourier	ç)
Y	MAGE	CON	II KESSION					

CO1: Apply image processing techniques in both the spatial and frequency (Fourier) domains.

Total instructional hours

CO2: Design image analysis techniques in the form of image segmentation and to evaluate the methodologies for segmentation.

Course Outcome

coding.

CO3: Independently design and carry out the image Filtering .

JPEG-MPEG-Quantization: scalar Quantization and vector Quantization-code word assignment: uniform length and variable length codeword assignment - differential pulse

code modulation, two channel coders, pyramid coding; hybrid transform coding - wavelet

CO4: Describe the image enhancement techniques.

CO5: Discuss the Restoration and Compression.

TEXT BOOKS:

T1. Gonzalez R.C. Woods R.E, "Digital Image Processing", Prentice Hall; 2007
 T2. Jain A.K., "Fundamentals of Digital Image Processing", Prentice Hall of India,1989

REFERENCE BOOKS:

R1. Kenneth R Castleman, "Digital Image Processing", Prentice Hall International, Inc., 2001.

R2. William K.Pratt,"Digital Image Processing", John Wiley & Sons, 2007.

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	\boldsymbol{C}
M.E.	16AP1302	WIRELESS MOBILE COMMUNICATION	3	0	0	3
Course Objective	 Understand the conc Recognize concepts 	s channel and its physical design. septs of digital modulation. in selection of channel. ncepts of various spread spectrum. systems.				

Unit	Description	Instructional hours
I	THE WIRELESS CHANNEL Overview of wireless systems – Physical modeling for wireless channels – Time and Frequency coherence – Statistical channel models – Capacity of wireless Channel-Capacity of Flat Fading Channel , Channel Distribution Information known – Channel Side Information at Receiver – Channel Side Information at Transmitter and Receiver – Capacity with Receiver diversity	9 .
II	PERFORMANCE OF DIGITAL MODULATION OVER WIRELESS CHANNEL Fading- Outage Probability- Average Probability of Error - Combined Outage and Average Error Probability - Doppler Spread - Inter symbol Interference	9
III	DIVERSITY Realization of Independent Fading Paths – Receiver Diversity – Selection Combining— Threshold Combining – Maximal-Ratio Combining – Equal - Gain Combining – Transmitter Diversity – Channel known at Transmitter – Channel unknown at Transmitter—The Alamouti Scheme.	9
IV	MULTICARRIER MODULATION Data Transmission using Multiple Carriers – Multicarrier Modulation with Overlapping Sub channels – Mitigation of Subcarrier Fading – Discrete Implementation of Multicarrier Modulation – Peak to average Power Ratio- Frequency and Timing offset – Case study IEEE 802.11a.	9
V	SPREAD SPECTRUM Spread Spectrum Principles – Direct Sequence Spread Spectrum – Spreading Codes Synchronization- RAKE receivers- Frequency Hopping Spread Spectrum – Multiuser DSSS Systems – Multiuser FHSS Systems	9
	Total instructional hours	45
Cou		e field of

Outcome

wireless networks.

CO4: Design and analyse the multicarrier modulation.

CO5: Impart the knowledge on the multiuser systems.

- T1. Andrea Goldsmith, Wireless Communications, Cambridge University Press, 2005.
- David Tse and Pramod Viswanath, Fundamentals of Wireless Communication, Cambridge University Press, 2005.

REFERENCE BOOKS:

- R1. W.C.Y.Lee, Mobile Communication Engineering, Mc Graw Hill, 2000.
- R2. A.Paulraj, R.Nabar, D.Gore, Introduction to Space-Time Wireless Communication, Cambridge University Press, 2003.

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PRO	GRAMME	;	COURSE CODE	NAME OF THE COURSE	L	T	P	C
14.5	,		16AP1303	INTELLIGENT CONTROL				
M.E	,.			AND ITS APPLICATIONS	3	0	0	3
Objective 2. 3. 4. 5.		1. 2. 3. 4. 5.	Impart the knowledge a	epts about Soft computing. e of Genetic Algorithm and Intelligenthout Neural Networks and Fuzzy Loon hybrid soft computing techniques.	ogic systems.	neering Ins	g. structi	onal
Unit			5	Description			hours	
I	Intelligence Important Fuzzy and theoretic optimizati	of ce-L Tec I So Ope on a	omputing-Soft Computering methods-taxon chnologies-Weights, Bioft Computing – Fuzirations. Genetic algorate search techniques	nting constituents and conventional A nomy-Evolution of neural networks as, Threshold, Learning rste- Introd zy Sets – Basic Definition and Te rithm- Introduction Biological back	-basic models- luction to Neuro – erminology – Set-		9	
II	Genetic A Stopping operators inheritance	lgor cor and	dition-constraints-Bui technologies-Geneti	e-general genetic algorithm-operator. Ilding block hypothesis, working ic modeling: Significance of Geleletion, Bitwise operator.GA optim)	principle, basic enetic operators,		9	
Ш	Machine Supervise Multilayer Learning l	Lead L d L r Pe Netv	earning Neural Netw erceptrons — Unsuperv works — Kohonen Self-	work, Adaptive Network-Feed F orks – Perceptrons - Adaline – I vised Learning Neural Networks – Organizing Networks – Learning Ve	Back propagation Competitive		9	
IV	value assi measures: fuzziness tables, fuz decision n	mbe gnm fu -fuz zzy naki	rship functions: fe tents- Defuzzification: zzy arithmetic – exte zzy integrals – fuzzy r reasoning-fuzzy infer ing.	atures, fuzzification, methods lambda cuts – methods – fuzzy ari ension principle – fuzzy measure, ule base and approximate reasoning ence systems-overview of fuzzy ex	s – measures of : truth values and : truth system-fuzzy		9	
V	Neuro-fuz fuzzy ger approach (TSP) usi	zy l netic of r ng	nybrid systems – gene hybrid systems – si nultispectral images w		fuzzy hybrid and cations: A fusion salesman problem		9	
Cou Outco	rse CC ome CC CC KT BOOKS J.S.R.Jan	02: 0 03: 1 04: 2 05: 2 8: g, C	Carry out about Intelli Explain about Neural I Acknowledge the func Apply the various appl C.T. Sun and E.Mizuta	peept about soft computing. gent control and its applications. Networks and Fuzzy Logic operation tion of Hybrid soft computing Technications of soft computing technique in, "Neuro-Fuzzy and Soft Computing Principles of Soft Computing". Wiles	s. niques. s in engineering. g", PHI / Pearson l	Educa		012

T2. S.N.Sivanandam and S.N.Deepa, "Principles of Soft Computing", Wiley India Pvt Ltd, 2011

REFERENCE BOOKS:

R1. L.Fortuna, G.Rizzotto, M.Lavorgna, G, Nunnari, M.G.Xibilia and R.Caponetto, "Soft Computing New Trends and Applications", Springer 2011.

R2. Fakhreddine O. Karray Clarence De Silva, "Soft Computing and Intelligent Systems-Design, Theory, Tools and Applications", Pearson Education 2009

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PROGRAMME		(COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	\mathbf{C}
М.	.E.		16AP1304	DIGITAL CONTROL ENGINEERING	3	0	0	3
Course Objective		1. 2. 3. 4. 5.	Introduce the z-dom Familiarize state var Analyze the stability	ligital control systems and sampling ain in digital control system. iable analysis of digital control syste of discrete time systems. ous design techniques on digital cont	ems.			
Unit				Description				uctional ours
I	INTRO	DU	CTION					
	systems principl Hold ci	s - D le of rcuits	Pigital control system sampling, quantization	nd time response analysis and spec is — basic concepts of sampled dat in and coding — Reconstruction of si of choice of sampling rate -Basic di- time systems.	a control s ignals – Sa	ystems – mple and	8	9
П,	MODELS OF DIGITAL CONTROL DEVICES AND SYSTEMS Z domain description of sampled continuous time plants — models of A/D and D/A converters — Z Domain description of systems with dead time — Implementation of digital controllers — Digital PID controllers — Position, velocity algorithms — Tuning — Zeigler — Nichols tuning method.						•	9
III	STATE VARIABLE ANALYSIS OF DIGITAL CONTROL SYSTEMS State space representation of discrete time systems – Solution of discrete time state space equation – State transition matrix – Decomposition techniques – Controllability and Observability – Multivariable discrete systems.							9
IV			Y ANALYSIS	and 7 ulana. Itamila stability to the D				0
v	criterio	n- Lia		and Z plane- Jury's stability test - R lysis of discrete time systems ROL SYSTEM	outh stabili	щу		9
	Frequer	icy re	esponse method - Sta	control system design — Digital co te feedback — Pole placement desig ency response — Kalman's filter.				9
	- Digita	11 1110	er properties—freque		instruction	al hours		45
Course Outcome		CO CO	2: Develop the difference3: Pertain the differenceanalysis.	vledge of sampling in digital control ent models and digital controllers of nt techniques to digital control system ses to observe the stability of the con- control system.	control sys	oncepts o	f State v	ariable

TEXT BOOKS:

- T1. Gopal M. "Digital Control and State Variable methods", Tata McGraw Hill Publishing Company Ltd., New Delhi, India, 2003.
- T2. M. Sami Fadali. "Digital Control Engineering Analysis and Design", Elsevier Inc, 2013.

REFERENCE BOOKS:

- R1. M.Gopal. "Digital Control Engineering", New age International (p) Ltd, 1999.
 R2. Ogata K. "Discrete Time Control Systems', Prentice Hall International", New jersey, USA, 2002.

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	L	T	P	C
M.E.	16AP1305	DSP INTEGRATED CIRCUITS	3	0	0	3
1.	Learn how DSP application	ns are implemented using VLSI Tech	nology.			

Course Objective 2. Compare and study the performance of various transforms for signal processing.

Design FIR and IIR filters for the given specifications.
 Impart the knowledge about DSP Processor Architecture using VLSI Technology.

5. Design Integrated circuits using VLSI Technology.

Unit	Description	Instructional hours
I	DSP INTEGARTED CIRCUITS AND VLSI CIRCUIT TECHNOLOGIES Standard digital signal processors, Application specific IC's for DSP, DSP systems, DSP system design, Integrated circuit design. MOS transistors, MOS logic, VLSI process technologies, Trends in CMOS technologies.	9
П	DIGITAL SIGNAL PROCESSING Digital signal processing, Sampling of analog signals, Selection of sample frequency, Signal-processing systems, Frequency response, Transfer functions, Signal flow graphs, Filter structures, Adaptive DSP algorithms, DFT-The Discrete Fourier Transform, FFT-The Fast Fourier Transform Algorithm, Image coding, Discrete cosine	9
Ш	transforms. DIGITAL FILTERS AND FINITE WORD LENGTH EFFECTS FIR filters, FIR filter structures, FIR chips, IIR filters, Specifications of IIR filters, Mapping of analog transfer functions, Mapping of analog filter structures, Multirate systems, Interpolation with an integer factor L, Sampling rate change with a ratio L/M, Multirate filters. Finite word length effects –Parasitic oscillations, Scaling of signal levels, Round-off noise, Measuring round-off noise, Coefficient sensitivity, Sensitivity	9
IV	and noise. DSP ARCHITECTURES AND SYNTHESIS OF DSP ARCHITECTURES DSP system architectures, Standard DSP architecture, Ideal DSP architectures, Multiprocessors and multicomputers, Systolic and Wave front arrays, Shared memory architectures. Mapping of DSP algorithms onto hardware, Implementation based on complex PEs, Shared memory architecture with Bit – serial PEs.	9
V	ARITHMETIC UNITS AND INTEGRATED CIRCUIT DESIGN Conventional number system, Redundant Number system, Residue Number System, Bit-parallel and Bit- Serial arithmetic, Basic shift accumulator, Reducing the memory size, Complex multipliers, Improved shift-accumulator. Layout of VLSI circuits, FFT processor, DCT processor and Interpolator as case studies. Total instructional hours	9 45
Cou Outc	CO1: Solve discrete-time transforms. CO2: Design FIR and IIR filters. CO3: Knowledge of spectral estimation and linear prediction.	-10

CO5: Design Integrated Circuits using VLSI Technology.

TEXT BOOKS:

- T1. Lars Wanhammer, "DSP Integrated Circuits", 1999 Academic press, New York
- T2. A.V.Oppenheim et.al, "Discrete-time Signal Processing", Pearson Education, 2000.

REFERENCE BOOKS:

- R1. Emmanuel C. Ifeachor, Barrie W. Jervis, "Digital signal processing A practical approach" Second Edition, Pearson Education, Asia.
- Keshab K.Parhi, "VLSI Digital Signal Processing Systems design and Implementation", John Wiley & Sons, 1999.

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PROFESSIONAL ELECTIVE II

PROGRAMME	\mathbf{C}	COURSE CODE	NAME OF THE COURSE	L	T	P	C
M.E.		16AP1306	CAD FOR VLSI CIRCUITS	3	0	0	3
Course Objective	1. 2. 3. 4.	Use the simulation techni	s behind the VLSI design rules and routing ques at various levels in VLSI design flow. of various algorithms used for floor planning.			ų	

Unit		Description	Instructional hours	
Ι	Introduc Review Comple	OF CAD ALGORITHMS ction to VLSI Design methodologies - Review of Data structures and algorithms — of VLSI Design automation tools - Algorithmic Graph Theory and Computational exity — Tractable and Intractable problems - General purpose methods for atorial optimization.	9	
II	Layout graph coalgorith	UT DESIGN ALGORITHMS Compaction - Design rules - Problem formulation - Algorithms for constraint ompaction - Placement and partitioning - Circuit representation - Placement	9	
III	Floor pi	AUGORITHMS lanning concepts - Shape functions and floorplan sizing - Types of local routing s -Area routing - Channel routing - Global routing - Algorithms for global routing.	9	
IV	SIMULATION AND SYNTHESIS ALGORITHMS Simulation - Gate-level modeling and simulation - Switch-level modeling and simulation - Combinational Logic Synthesis - Binary Decision Diagrams - Two Level Logic Synthesis.			
V	High le	CM MODELING ALGORITHMS vel Synthesis - Hardware models - Internal representation - Allocation - ment and scheduling - Simple scheduling algorithm - Assignment problem – High ansformations.	9	
	icvei ii	Total instructional hours	45	
	ourse come	 CO1: Demonstrate advanced knowledge in design techniques. CO2: Analyze and understand the design algorithms. CO3: Apply advanced simulation methods for design circuits. CO4: Understand the concepts of various algorithms used for floor planning and rout techniques. CO5: Study of high level transformation. 	ing	

- T1. S.H. Gerez, "Algorithms for VLSI Design Automation", John Wiley & Sons, 2 Edition, 2006.
 T2. N.A. Sherwani, "Algorithms for VLSI Physical Design Automation", Kluwar Academic Publishers, 2002.

REFERENCE BOOKS:

- R1. Drechsler, R., Evolutionary Algorithms for VLSI CAD, Kluwer Academic Publishers, Boston, 1998.
 R2. Eugene D.Fabricius, "Introduction to VLSI Design", McGraw Hill International Editions, 1990.

EEE - HICET

PROGRAMME		E COURSE CODE NAME OF THE C		L	T	P	C
M.E.		16AP1307	MULTICORE ARCHITECTURES	3	0	0	3
Course Objective	1. 2. 3. 4. 5.	related parameters. Expose the students to the Understand the different	arallel processing. nds in the field of Computer Architect problems related to multiprocessing. types of multicore architectures. archouse-scale and embedded architectures.		entify p	erforn	nance

Unit	Description	Instructional hours
I	FUNDAMENTALS OF QUANTITATIVE DESIGN AND ANALYSIS	
	Classes of Computers - Trends in Technology, Power, Energy and Cost - Dependability -	
	Measuring, Reporting and Summarizing Performance - Quantitative Principles of	9
	Computer Design - Classes of Parallelism - ILP, DLP, TLP and RLP - Multithreading -	
	SMT and CMP Architectures – Limitations of Single Core Processors - The Multicore era.	
II	DLP IN VECTOR, SIMD AND GPU ARCHITECTURES	
	Introduction- Vector Architecture - SIMD Instruction Set Extensions for Multimedia -	9
	Graphics Processing Units - Detecting and Enhancing Loop Level Parallelism.	
III	TLP AND MULTIPROCESSORS	
	Introduction- Centralized shared memory Architectures- Symmetric and Distributed	
	Shared Memory Architectures – Cache Coherence Issues - Performance Issues –	9
	Synchronization Issues - Models of Memory Consistency - Interconnection Networks -	
	Buses, Crossbar and Multi-stage Interconnection Networks.	
IV	RLP AND DLP IN WAREHOUSE-SCALE ARCHITECTURES	
	Introduction- Programming Models and Workloads for Warehouse-Scale Computers -	9
	Architectures for Warehouse-Scale Computing – Physical Infrastructure and Costs –	
	Cloud Computing.	
V	ARCHITECTURES FOR EMBEDDED SYSTEMS	0
	Features and Requirements of Embedded Systems - Signal Processing and Embedded	9
	Applications – The Digital Signal Processor – Embedded Multiprocessors	45
	Total instructional hours	45
	CO1: Identify the limitations of ILP and the need for multicore architectures.	
	CO2: Discuss the issues related to multiprocessing and suggest solutions.	
Cour	rse CO3: Point out the salient features of different multicore architectures and how they ex	ploit
Outco	ome Parallelism.	
	CO4: Develop the knowledge of embedded system.	
	CO5: Analyse the embedded based architectures.	

TEXT BOOKS:

TI. John L. Hennessey and David A. Patterson, "Computer Architecture – A Quantitative Approach", Morgan Kaufmann / Elsevier, 5th edition, 2012.

REFERENCE BOOKS:

R1. Kai Hwang, "Advanced Computer Architecture", Tata McGraw-Hill Education, 2003.
R2. Richard Y. Kain, "Advanced Computer Architecture a Systems Design Approach", Prentice Hall, 2011.



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PROGRAMME		1ME	ME COURSE CODE NAME OF THE COURSE L			T	P	C
	M.E.		16AP1308	QUANTUM ELECTRONICS	3	0	0	3
Cou Obje	arse ctive	2. 3. 4.	Know the concepts of EM fie Study the types of lasers and Learn the concept of Non-lin Identify the various methods Gain knowledge of the conce	its characteristics ear optics				
Unit			De	scription		Instr h	uctio ours	nal
I	Introdu quantum Effectiv Directiv Schrod and the	nction m el ve In onal ingen ir qu	n to Quantum Electronics-His lectronics-Planar-mirror wave dex Method-Guided wave co coupler-Mode coupling in p	F QUANTUM MECHANICS story of quantum electronics-Recent progree eguides-Modes in dielectric slab wavegu pupling and Interference-Coupled Mode The eriodic waveguides-Mode Interference-The ulation of quantum mechanics-Lattice vibratelds and their quantization.	ides- eory- e		9	
	LASER Gaussian beam in a homogenous medium, lens waveguide, Elliptic Gaussian beams, Optical resonators, Spontaneous and induced transitions, gain coefficient, homogenous and inhomogeneous broadening, Laser oscillations, Semiconductor laser, quantum well laser, modulation of optical radiation, Q switching and Mode locking of laser, Quantum wires and dots, Laser arrays-Laser Oscillation-specific laser systems-semiconductor diode lasers-Quantum well lasers- Free electron laser.							
III	Introdu Electro general Birefrii Optical retarda	nction omag tion, ngen l sol	netic Formulation of the N parametric amplification, ce and Quasi- Phase Matchi iton-Electro-optic (EO) mod	The nonlinear optical susceptibility te fonlinear Interaction-Optical Second harm parametric oscillations — conservation ling-3 rd order NL effects-Self-Phase Modula fullation of light-Linear EO effect, Phase action-Traveling wave modulator	nonic laws-		9	
IV	Introdu Stimul	action	n-Stimulated Molecular Ram	an scattering, Electromagnetic treatment o kes scattering, Stimulated Brillouin scatte	f ring,		9	
V	NOISI Noise	E AN in la	ND SPECTRA OF LASER A ser amplifiers-Spontaneous	AMPLIFIERS AND OSCILLATORS Emission Noise in Laser Oscillators - L α Parameter - Measurement of (Δν)l _{soer} .			9	
Cou	•	CC	ol: Appreciate the importance of 2: Realize the importance of 3: Gain knowledge about nor 4: Understand the concepts of 5: Identify the noise in ampli	Total instructional has of wave guides. laser. n linear optics and its types. of scattering.	ours		45	

TEXT BOOKS:

T1. Amnon Yariv, "Quantum Electronics", John Wiley 1989.
T2. Max Schubert, Bernd Wilhelmi, "Nonlinear optics and quantum electronics", Wiley-Interscience 1986.

REFERENCE BOOKS:
R1. D.Marcuse, "Principle of Quantum Electronics", Cambridge 1980.
R2. Max Schubert, Bernd Wilhelmi, "Nonlinear optics and quantum electronics", Wiley-Interscience 1986.

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	C
M.E.	16AP1309	SENSORS AND SIGNAL CONDITIONING	3	0	0	3
Course Objective	 Acquire knowledge Analyse various sig Impart knowledge a 	nd dynamic characteristics of measurem about various types of sensors viz. Resi nal conditioning circuits. bout different types digital sensors. actor sensors and special sensors.			- generat	ing.

Unit	Description	Instructional hours
Ι	INTRODUCTION TO MEASUREMENT SYSTEMS Introduction to measurement systems: general concepts and terminology, measurement systems, sensor classification, errors, static characteristics of measurement systems, accuracy, precision, sensitivity, linearity, resolution, dynamic characteristics of zero-order, first-order, and second-order measurement systems.	9
II	RESISTIVE SENSORS Resistive sensors: potentiometer, strain gauges and types, resistive temperature detector(RTD), thermistor, light-dependent resistors(LDR); Signal conditioning for resistive sensors: measurement of resistance, voltage dividers, Wheatstone bridge, sensor bridge calibration and compensation, differential amplifier, instrumentation amplifier. REACTIVE SENSORS	9
	Reactance variation and electromagnetic sensors: capacitive sensors, inductive sensors – reluctance variation, eddy current, linear variable differential transformers (LVDTs), electromagnetic sensors – sensors based on faraday's law, hall effect sensor; Signal conditioning for capacitive sensors, carrier amplifiers – application to the LVDT.	9
IV V	SELF-GENERATING SENSORS Self-generating sensors: thermoelectric sensors, piezoelectric sensors, pyroelectric sensors, photovoltaic sensors, electrochemical sensors, Signal conditioning for self-generating sensors: chopper amplifiers, electrometer amplifiers, charge amplifiers. DIGITAL SENSORS AND SEMICONDUCTOR DEVICE SENSORS	9
	Digital sensors: position encoders, resonant sensors –vibrating wire strain gauges, digital flow meters, thermometers based on semiconductor junctions, photodiodes and phototransistors, charge-coupled sensors – types of CCD imaging sensors, ultrasonic-based sensors, fiber-optic sensors.	9
	Total instructional hours	45
Co	CO1: Analyse the static and dynamic characteristics of measurement systems. CO2: Acquire knowledge about the various types of sensors viz. Resistive, Reactive generating and their signal conditioning.	re, Self-

Course Outcome

CO3: Examine various signal conditioning circuits.

CO4: Impart knowledge about different types digital sensors.

CO5: Illustrate semiconductor sensors and special sensors.

- T1. Ramon Pallás Areny, John G. Webster, "Sensors and Signal Conditioning", 2nd edition, John Wiley and Sons, 2000.
- T2. D.Patranabis, "Sensors and Transducers", Tata McGraw Hill Publications, 2003.

REFERENCE BOOKS:

- R1. E.O. Doeblin, "Measurement System: Applications and Design", McGraw Hill Publications.
 R2. C.D. Johnson, "Process Control Instrumentation Technology", John Wiley and Sons.

PROGRAMME		ME	COURSE CODE	NAME OF THE COURSE	L	Т	P	C
1110	M.E.		16AP1310	SEMICONDUCTOR MEMORY DESIGN AND TESTING	3	0	0	3
Objective 2. 3.		1. 2. 3. 4. 5.	Study the fault modeling		iemories		ruction	nal
Unit				Description		hours		
I	Static Archite Technology and To (DRA) Advan DRAN	Rand ectur ologi echno Ms): aced	e-MOS SRAM Cell and I es-Silicon On Insulator ologies-Application Speci DRAM Technology Dev Cell Strucutures-BiCMOS signs and Architecture-Ap	ECHNOLOGIES GRAMs): SRAM Cell Structures-MOS SRA Peripheral Circuit Operation-Bipolar SRAM (SOI) Technology-Advanced SRAM Archi fic SRAMs. Dynamic Random Access Me elopment-CMOS DRAMs DRAMs Cell The s, DRAMs-Soft Error Failures in DRAMs-Ac oplication, Specific DRAMs.	tectures mories ory and		9	
II	Maske Memo Read- (OTP) Archit	ed R ries Only EPF ectur	(PROMs)-BipolarPROMs Memories (EPROMs)-Fl ROMs-Electrically Erasab	Ms)-High Density ROMs-Programmable Reaction PROMs-Erasable (UV) - Programmoating-Gate EPROM Cell-One-Time Programle PROMs (EEPROMs)-EEPROM Technologish Memories (EPROMs or EEPROM)-Action	nable mmable ogy And		9	
Ш	MEM RAM Testin	ORY Fau g No	FAULT MODELING,	TESTING AND FAULT TOLERANCE Testing, Pseudo Random Testing-Megabit ing and Testing-IDDQ Fault Modeling And Testing And	DRAM Festing-		9	
IV	RELI Gener Reliab Screer Pheno Design	ABI al Re bility ning meno n Is	LITY AND RADIATION cliability Issues - RAM Fa Modeling and Failure Rat and Qualification. Rad on (SEP) - Radiation Hard ssues-Radiation Harden and Testing - Radiation		etures-Re cess and Iardness	eliabili	ty- ity 9	
V	ADVA TECH Ferroe Analo Memo	ANC INO electr g M ories Mem	ED MEMORY TECHNOLOGIES ic Random Access Mem femories-Magneto resist (MRAMs)-Experimental ory Stacks and MCMs (ories (FRAMs)-Gallium Arsenide (GaAs) Five Random Access Memories-Random Memory Devices. Memory Hybrids and 3D)-Memory MCM Testing and Reliability Packaging Future Directions.	Access MCMs		9	r
Out	urse come	CO CO CO CO CO	1: Study the architectures 2: Learn the knowledge a 3:Acquire knowledge abo 4: Impart the concepts of 5: Familiarize the memor	for SRAM, DRAM and non-volatile memoric bout the fault modeling and testing of memor ut radiation hardening process and issues for advanced memory technologies and packing t y technology and packaging technologies.	es. ies for fa memory echnolog	ault de gies.		

T1. Ashok K.Sharma, "Semiconductor Memories Technology, Testing and Reliability ",Prentice Hall of India Private Limited, New Delhi, 1997.

REFERENCE BOOKS:
R1. Luecke Mize Care, "Semiconductor Memory design & application", Mc-Graw Hill.
R2. Betty Prince, "Emerging Memories: Technologies and Trends", Kluwer Academic publishers, 2002



PROFESSIONAL ELECTIVE III

PROGRAMME	COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	\mathbf{C}	
M.E.	16AP2301	VLSI DESIGN TECHNIQUES	3	0	0	3	
Course Objective	 Study the basic of MOS Circuits Design and carry out the MOS Process Technology. Learn the VLSI fabrication and lay out designing the operation of MOS devices Impart in-depth knowledge about analog and digital CMOS circuits. The depth knowledge about the logic design 						

Unit	Description	Instructional hours
Ι	OVERVIEW OF VLSI DESIGN METHODOLOGY VLSI design process - Architectural design - Logical design - Physical design -	9
II	Layout styles - Full custom - Semicustom approaches. BASIC ELECTRICAL PROPERTIES OF MOS AND CMOS CIRCUITS MOS transistor - Threshold voltage equations -Basic DC equations - Second order	
	effects - MOS models - Small signal AC characteristics - NMOS inverter - Depletion mode and enhancement mode pull ups - CMOS inverter - DC characteristics - Inverter delay - Pass transistor - Transmission gate -Power consumption in CMOS gates - Static dissipation - Dynamic Dissipation.	9
III	VLSI FABRICATION TECHNIQUES AND LAYOUT DESIGN RULES	
IV	An overview of wafer fabrication – Wafer processing - Oxidation - Patterning – Diffusion - Ion implantation - Deposition – Silicon gate NMOS process - CMOS processe - NWell - PWell - Twintub - Silicon on insulator - CMOS process enhancements - Interconnect - Circuit elements- Latch up - Latchup prevention techniques. Need for design rules - Mead Conway design rules for the silicon gate NMOS process – CMOS based design rules LOGIC DESIGN	9
1 V	Switch logic - Pass transistor and transmission gate based design - Gate logic -	
	Inverter - Two input NAND gate - NOR gate - Other forms of CMOS logic - Dynamic CMOS logic - Clocked CMOS logic - Precharged domino CMOS logic - Structured design - Simple combinational logic design examples - Parity generator - Multiplexers - Clocked sequential circuits - Two phase clocking - Charge storage - Dynamic register element - NMOS and CMOS - Dynamic shift register -Semistatic register - JK flip flop circuit.	9
V	SUBSYSTEM DESIGN PROCESS	_
	General arrangement of a 4-bit arithmetic processor - Design of a 4bit shifter - Design of a ALU subsystem - Implementing ALU functions with an adder - Carry look ahead adders - Multipliers - Serial parallel multipliers - Pipelined multiplier array - Modified Booth's algorithm - Incrementer / Decrementer.	9
	Total instructional hours	45
	CO1: Analysis the operation of CMOS	

Course

CO2: Study of the design rules and layout diagram.

Outcome

CO3: Design of basic electrical properties of mos and cmos circuits

CO4: Impart in-depth knowledge about analog and digital CMOS circuits.

TEXT BOOKS: CO5: Apply and implementing of the logic design.

- T1. Kamran Eshraghian, Douglas A. Pucknell, Essentials of VLSI Circuits and Systems, Prentice Hall of India,
- T2. Neil Weste and Kamran Eshranghian, Principles of CMOS VLSI Design, Addison Wiley, 2012.

REFERENCE BOOKS:

- R1. Jan M Rabaey, Digital Integrated Circuits- A Design, Prentice Hall, 2009
 R2. S. Srinivasan, VLSI Circuits, NPTEL Courseware, 2005.

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PROGRAMME		COURSE CODE	NAME OF THE COURSE	L	T	P	\boldsymbol{C}
M.E.		16AP2302	EMBEDDED NETWORKING	3	0	0	3
Course Objective	1. 2. 3. 4. 5.	4. Basic knowledge about elements of a network			S		

Unit	Description	Instructional hours
Ι	COMMUNICATION PROTOCOLS Serial/Parallel Communication – Serial communication protocols -RS232 standard – RS485 – Synchronous Serial Protocols -Serial Peripheral Interface (SPI) – Inter Integrated Circuits (I2C) – PC Parallel port programming - ISA/PCI Bus protocols – Firewire.	9
II	USB AND CAN BUS USB bus – Introduction – Speed Identification on the bus – USB States – USB bus communication: Packets –Data flow types –Enumeration –Descriptors –PIC Microcontroller USB Interface – CAN Bus – Introduction - Frames –Bit stuffing –Types of errors –Nominal Bit Timing – PIC microcontroller CAN Interface –A simple application with CAN.	9
111	ETHERNET BASICS Elements of a network – Inside Ethernet – Building a Network: Hardware options – Cables, Connections and network speed – Design choices: Selecting components – Ethernet Controllers – Using the internet in local and internet communications.	9 -
IV	EMBEDDED ETHERNET Exchanging messages using UDP and TCP – Serving web pages with Dynamic Data – Serving web pages that respond to user Input – Email for Embedded Systems – Using FTP – Keeping Devices and Network secure.	9
V	WIRELESS EMBEDDED NETWORKING Wireless sensor networks — Introduction — Applications — Network Topology — Localization — Time Synchronization - Energy efficient MAC protocols — SMAC — Energy efficient and robust routing — Data Centric routing.	9
	Total instructional hours	45
101.0	urse come CO1: Complete knowledge of wired and wireless network protocols. CO2: Should be able to incorporate networks in embedded systems. CO3: Apply the TCP,IP,ISA client server protocols for embedded networks. CO4: Design and carry out the basic knowledge about elements of a network. CO5: Independently design and carry out Wireless sensor network communication	ı protocols.

- T1. Frank Vahid, Tony Givargis, "Embedded Systems Design: A Unified Hardware/Software Introduction" John & Wiley Publications, 2002.
- Jan Axelson, "Parallel Port Complete: Programming, interfacing and using the PCs parallel printer port" -Penram Publications, 1999

REFERENCE BOOKS:

- R1. Dogan Ibrahim, "Advanced PIC microcontroller projects in C: from USB to RTOS with the PIC18F series" - Elsevier 2008.
- R2. Jan Axelson, "Embedded Ethernet and Internet Complete", Penram publications, 2003.

PROGRAMME	COURSE CODE	NAME OF THE COURSE	L	T	P	\mathbf{C}
M.E.	16AP2303	FIBER OPTIC SENSORS	3	0	0	3
Course Objective	 Explore the fiber Gra Discuss the types of G Compare the use of G 	entals of Fiber Optic Sensor Technology ting Sensors. listributed and magnetic sensors. Themical and Bio sensors. ations of fiber optic sensors.	7.			

Unit	Description	Instructional hours	
Ι	SENSOR TECHNOLOGY The Emergence of Fiber Optic Sensor Technology -Introduction to Optical Fibers- Types of optical Fibers , Step-Index single mode and multimode Fiber - Intensity- Based and Interferometric Sensors - Fabry perot, Mach Zender, Michelson and Sagnac.	9	
П	GRATING SENSORS Multimode Grating and Polarisation Sensors-Sensors Based on Relative Movement of Opposed Gratings-Grating Period Modulation-Sensors Based on the Photoelastic Effect- Retardation Plates-Fiber Grating Sensors.	9	
III	DISTRIBUTED AND MAGNETIC SENSORS Fiber Optic Distributed and Magnetic Sensor-Distributed Sensing- Basic Principles of Sensor Multiplexing- Interferometric Sensor Multiplexing- Faraday effect sensors-Magneto strictive - Lorentz force sensors-Evanescent Field Absorption Sensors	9	
IV V	CHEMICAL AND BIOSENSOR Fiber Optic Chemical and Biosensor: Reagent Mediated sensor-Humidity sensor – pH sensor - Hydrogen sensor - CO ₂ sensor – Ammonia sensor - Chloride sensor – Glucose sensor – Oxygen sensor - Surface Plasmonic Resonance based sensor.	9	
*	APPLICATIONS Industrial Applications of Fiber Optic Sensors: Temperature - Pressure - Fluid level - flow - Position - Vibration - Rotation measurements - Current - Voltage		
	measurement – Chemical analysis Total instructional hours	45	
Cou Outc	CO3: Illustrate the types of distributed and magnetic sensors		

- T1. Eric Udd, William B. Spillman, Jr., "Fiber Optic Sensors: An Introduction for Engineers and Scientists", John Wiley & Sons 2011.
- T2. Francis T.S. Yu, Shizhuo Yin, Paul B. Ruffin, "Fiber Optic Sensors", CRC Press Publisher 2010.

REFERENCE BOOKS:

- R1. Bhagavānadāsa Gupta, Banshi Das Gupta, "Fiber Optic Sensors: Principles and Applications", New India Publishing 2006.
- R2. David A. Krohn, "Fiber optic sensors: fundamentals and applications", ISA Publishing 2000.

Chairman SELECTOR OF THE PROPERTY OF THE PROPE

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	L	T	P	C		
M.E.	16AP2304	NEURAL NETWORKS AND ITS APPLICATIONS	3	0	0	3		
Course Objective	 Impart knowledge Survey attractive Study the self org 	 Introduce the basic knowledge about neural networks. Impart knowledge on various learning processes and propagation techniques. Survey attractive applications of artificial neural networks. 						

Unit	Description	Instructional hours
I	INTRODUCTION	nours
	What is neural network? Human brain - models of a neuron - neural network viewed as directed graph - network architectures- knowledge representation- artificial intelligence and neural networks- error correction learning.	9
II	LEARNING PROCESS AND SINGLE LAYER PERCEPTION Competitive-Boltzmann learning-credit assignment problem-Memory-adaption-adaptive filtering problem-unconstrained organization techniques-least mean square algorithm-convergence theorem-relation between perception and bayes classifier for a Gaussian environment-engineering applications.	9
III	BACK PROPAGATION Back propagation algorithm XOR problem-heuristics-output representation and decision rule-back propagation and differentiation-hessian matrix - generalization-cross validation-network pruning techniques-virtues and limitations of back propagation learning-back propagation network applications.	9
14	SELF ORGANISATION MAPS Two basic feature mapping models-self organization map-SOM algorithm-properties of feature map-computer simulations-learning vector quantization- adaptive patter classification-hierarchal vector quantilizer - contexmel maps -applications of self organizing maps.	9
V	NEURO DYNAMICS Dynamical system- stavility of equilibrium states-attractors-neuro dynamical models-manipulation of attractors' as a recurrent network paradigm –Hopfield models-Hopfield networks applied to travelling salesman problem	9
	Total instructional hours	45
Cou Outo	CO1: Apply the basic knowledge of neural networks on engineering applications CO2: Recall various learning processes in neural networks and its applications. CO3: Analyze self organization maps and their applications. CO4: Apply neural networks in real time applications. CO5: Pertain various applications of neuro dynamics	

- T1. Simon Haykin, "Neural Networks A Comprehensive foundation", Pearson education, second edition,2004.
- James A. Freeman, David M.Skapura, "Neural Network Algorithm, Applications and Programming Techniques", Pearson education, 2007.

REFERENCE BOOKS:

- R1. Huajin Tang, Kay chen Tan, Zhang Yi, "Neural Networks: Computational Models and Applications", Springer, 2010.
- R2. James A. Anderson, "An Introduction to Neural Networks", prentice-hall of India pvt.ltd.2002.
 R3. S.N. Sivanandam, S.Sumathi, S.N.Deepa, "Introduction to Fuzzy Logic using MATLAB", Springer,2003

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PROGRAMME M.E.		COURSE CODE 16AP2305	NAME OF THE COURSE MEDICAL IMAGING TECHNIQUES		T P 0 0	C 3
Course Objecti	3.	 Study the functioning of radioisotopic imaging equipments. Know about MRI, image acquisition and reconstruction and MRI safety. Gain the mathematical concept needed in image processing. 				
Unit	nit Description				etional urs	
I PRINCIPLES OF RADIOGRAPHIC EQUIPMENT X-Ray tubes, cooling systems, removal of scatters, Fluoroscopy-construction of image Intensifier tubes, angiographic setup, mammography, digital radiology, DSA.					9	
II	The second of th					9

Emission tomography, SPECT, PET/CT ULTRASONIC SYSTEMS IV Wave propagation and interaction in Biological tissues, Acoustic radiation fields, 9 continuous and pulsed excitation, Transducers and imaging systems, Scanning methods, Imaging Modes, Principles and theory of image generation MAGNETIC RESONANCE IMAGING V NMR, Principles of MRI, Relaxation processes and their measurements, Pulse 9 sequencing and MR image acquisition, MRI Instrumentation, Functional MRI Total instructional hours 45

CO1: Domain knowledge about the various Medical Imaging techniques.

Alpha, Beta and Gamma radiation, Radiation detectors, Radio isotopic imaging equipments, Radio nuclides for imaging, Gamma ray camera, scanners, Positron

CO2: Explain the various diagnostic applications of the medical imaging techniques.

Course Outcome

III

CO3: Acquired the knowledge about the functioning of radio isotopic imaging equipments, MRI, image acquisition and reconstruction and MRI safety.

CO4: Understand the mathematical and medical concept needed in image processing.

CO5: Analyse the ultrasonic systems.

Projection. Artifacts, Principle of 3D imaging

RADIO ISOTOPIC IMAGING

TEXT BOOKS:

- T1. D.N.Chesney and M.O.Chesney Radio graphic imaging, CBS Publications, New Delhi, 1987.
- T2. Peggy, W., Roger D.Ferimarch, MRI for Technologists, Mc Graw Hill, New York, 1995.

REFERENCE BOOKS:

- R1. Steve Webb, The Physics of Medical Imaging, Taylor & Francis, New York.1988
- Donald W.McRobbice, Elizabeth A.Moore, Martin J.Grave and Martin R.Prince MRI from picture to proton, Cambridge University press, New York 2006.
- Jerry L.Prince and Jnathan M.Links, Medical Imaging Signals and Systems I-Pearson Education Inc. R3.

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PROFESSIONAL ELECTIVE IV

PROGRAMM	\mathbf{E}	COURSE CODE	NAME OF THE COURSE	L	T	P	C
M.E.		16AP2306	LOW POWER VLSI DESIGN	3	0	0	3
Course Objective	3.	Identify the various power le Categorize the power reduct Employ suitable techniques Design memory circuits with Use software in VLSI design	tion techniques based on optimization. to reduce the power losses. h less power losses.				

Unit	Description	Instructional hours	
Ι	LOW POWER CMOS VLSI DESIGN Basic principles and limits of low power VLSI design—Sources of Power dissipation Physics of Power dissipation in CMOS FET devices — Power Dissipation in CMOS Short Circuit, Dynamic, Load Capacitance	9	
II	POWER OPTIMIZATION Pre Computation Based Optimization - Logic Level Power Optimization - FSM and Combinational Logic Synthesis - Technology Mapping - Circuit Level Optimization - Circuit Level Transforms - CMOS Gate - Transistor Sizing.	9	
III	DESIGN AND TEST OF LOW VOLTAGE CMOS CIRCUITS Circuit Design Style- Leakage current in deep sub micrometer transistors- Deep sub micrometer device design issue- low voltage circuit design techniques-Testing deep sub micrometer ICs with elevated intrinsic leakage.	9	
IV	POWER ESTIMATION Power Estimation Techniques –Probabilistic –Statistical – Power Sensitivity Estimation -Estimation Glitching Power –Power Estimation Using Input Vector Compaction – Genetic Algorithm Maximum Power Estimation Strategies Power Saving in	9	
V	Interconnect. V SYNTHESIS AND SOFTWARE DESIGN FOR LOW POWER Behavioral level transforms - Sources of Power dissipation — Software power Estimation — Software power optimization — Automated Low power Code Generation — Co-design for low power.		
Cou Outc	CO3: Select Suitable techniques and adopt them to reduce the bower loss.	45	

TEXT BOOKS:

- T1. Kaushik Roy and S.C.Prasad, "Low power CMOS VLSI circuit design", Wiley, 2000. Kluwer, 2002.
 T2. Dimitrios Soudris, Chirstian Pignet, Costas Goutis, "Designing CMOS Kluwer, 2002

- REFERENCE BOOKS:
 R1. J.B.Kulo and J.H.Lou, "Low voltage CMOS VLSI Circuits", Wiley 1999.
 R2. A.P.Chandrasekaran and R.W.Broadersen, "Low power digital CMOS design", Kluwer, 1995.
 R3. Chirstian Pignet "Low Power CMOS Circuits" CRC Press, Taylor & Francis Group, 2010.

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	\mathbf{C}
M.E.	16AP2307	RESEARCH METHODOLOGY	3	0	0	3
1 Impart scientific knowledge for carrying out research work effectively						

2. Study about the various Research Design. Course

3. Acquire knowledge about Experimental design and Data collection Objective

Provide knowledge in multivariate analysis techniques

5. Discuss about the Research Practices and Report writing.

Unit	Description	Instructional hours
I	INTRODUCTION TO RESEARCH Research-Definition-Objectives of research, Meaning of research- Characteristics of research-Importance of research activities- Types of research-Research approaches- Significance-Problems in research- Qualities of good researcher- Research process-Problem encountered by researchers in India.	9
II	RESEARCH DESIGN The nature of research designs-Formulation of the research design: Process-classification of research designs-Exploratory-Secondary resource analysis-Two-tired research design-Concepts used in experiments-Validity in experimentation-factors affecting external validity-classification of experimental design-Pre-experimental-Quasi-experimental designs.	9
III	DATA COLLECTION METHODS Classification of Data-Collection of primary data-Observation-Interview method-Collection of data through Questionnaires-schedules-collection of secondary data-Research applications of secondary data-Benefits and drawbacks-classification of secondary data-Internal –External data sources-Presentation of data.	9
IV	MULTIVARIATE ANALYSIS TECHNIQUES Growth of Multivariate techniques-Characteristics and applications-Classification- Variables in multivariate analysis-Important multivariate techniques-Factor analysis- Rotation in factor analysis-R-type and Q type factor analysis-Path analysis.	9
V	RESEARCH PRACTICE AND REPORT WRITING. Literature review-Conference proceedings-Journals-Journal Impact Factor(JFI)-Citation index-h-index-Significance of report writing-Different steps in writing report-Layout of report writing-Types of reports-Mechanics of writing a research report-precautions for writing research reports-Conclusion and Scope for future work-Oral presentation.	9
	Total instructional hours	45
Cou Outc	CO3: Acknowledge the function of Multivariate Analysis Techniques	ively.

TEXT BOOKS:

- C.R.Kothari, Research Methodology Methods & Techniques, NEW Age International (P) Limited, New Delhi, 2007.
- Dr.Deepak Chawla, Dr. Neena Sondhi, Research Methodology concepts and cases, Vikas Publishing House Pvt. Ltd.New Delhi, 2011

REFERENCE BOOKS:

- R1. K.Prathapan, Research Methodology for Scientific Research, I.K.International Publishing House Pvt.Ltd. New Delhi, 2014L.
- R2. R.Panneerselvam, Research Methodology, PHI Learning Private Limited, New Delhi, 2011.
- R3. Donald H.McBurney, Research Methods, Thomson Asia Pvt. Ltd. Singapore, 2002.

PROGRAMME		ME	COURSE CODE	NAME OF THE COURSE	L	T	P	C
	M.E.		16AP2308	SOLID STATE DEVICE MODELING AND SIMULATION	3	0	0	3
1. 2. Course 3. Objective 4. 5.			Study principles of devi Performance under varie Apply the design and m Impart the knowledge of	als of circuit design and device modeling. ce modeling where in device physics and expre ous scenarios of excitation. odeling of Noise Modeling f BSIM mosfet modeling. y used device models used by the industry incl				EKV
Unit				Description		Instr	uctio ours	
I	MOSEE	TD	EVICE PHYSICS				0415	
	MOSFET DEVICE PHYSICS MOSFET capacitor, Basic operation, Basic modeling, Advanced MOSFET modeling, RF modeling of MOS transistors, Equivalent circuit representation of MOS transistor, High frequency behavior of MOS transistor and A.C small signal modeling, model parameter extraction, modeling parasitic BJT, Resistors, Capacitors, Inductors.							
П	Basic modeling, SPICE Level - 1, 2 and 3 models, Short channel effects, Advanced MOSFET modeling, RF modeling of MOS transistors, Equivalent circuit representation of MOS transistor, High frequency behavior of MOS transistor and A.C small signal							
Ш	modeling. NOISE MODELING Noise sources in MOSFET, Flicker noise modeling, Thermal noise modeling, model for accurate distortion analysis, nonlinearities in CMOS devices and modeling, calculation of distortion in analysis.						9	
IV	distortion in analog CMOS circuit. BSIM4 MOSFET MODELING Gate dielectric model, Enhanced mode I for effective DC and AC channel length and width, Threshold voltage model, Channel charge model, Mobility model, source/drain resistance model, I - V model, gate tunneling current model, substrate current models, Capacitance models, High speed model, RF model, Noise model, Junction diode models, Layout - dependent parasitic model.							
V	OTHER MOSFET MODELS The EKV model, model features, long channel drain current model, modeling second order effects of the drain current, modeling of charge storage effects, Non – quasi static modeling, Noise model, temperature effects, MOS model 9, MOSAI model, PSP model,						9	
	Influenc	e of	process variation, Model	ing of device mismatch for Analog/RF Applicat Total instructional	ions. hours		45	
	CO1: Gain the basic circuit design and device modeling for analysis. CO2: Acquire principles of device modeling and device performance under vario excitation. CO3: Design the high speed model of MOSFET. CO4: Adequate the most widely used device models used by the industry include EKV models.							

- EKV models.
 CO5: Study the EKV models of MOS semiconductors.

- Trond Ytterdal, Yuhua Cheng and Tor A. Fjeldly, Wayne Wolf, "Device Modeling for Analog and RF CMOS Circuit Design", John Wiley & Sons Ltd.
 Selberherr, S., "Analysis and Simulation of Semiconductor Devices", Springer Verlag., 1984.

REFERENCE BOOKS:

- R1. Arora, N., "MOSFET Models for VLSI Circuit Simulation", Springer Verlag, 1993.
- B.G.Streetman and S. Banarjee, "Solid State Electronic Devices", Prentice Hall of India Pvt. Ltd, New Delhi, India.
- R3. B. Bhattacharyya, "Compact MOSFET Models for VLSI Design", John Wiley & Sons Inc., 2009.

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PROGRAMME		COURSE CODE	NAME OF THE COURSE	${f L}$	T	P	C	
M	I.E.	16AP2309	HIGH PERFORMANCE NETWORKS	3	0	0	3	
	Course Objective 1. Develop a comprehensive understanding of multimedia networking. 2. Study the types of VPN and tunneling protocols for security. 3. Learn about network security in many layers and network management. 4. Study the concept of SMI, MIB & SNMP. 5. Impart the knowledge on network security and management.							
Unit			Description		Ins	Instructional hours		
Ι		RKING BASICS				nour	•	
	– review o	f network models, Switch DSL – ISDN – BISDN, A			Ĺ	9		
II	MULTIMEDIA NETWORKING APPLICATIONS Streaming stored and live Audio and Video – Best effort service and its limitations – real interactive audio and video, protocols— audio and video compression – beyond best effort service – scheduling and policing mechanism – integrated services –RSVP-differentiated services.							
III	ADVANCED NETWORKS CONCEPTS VPN-Remote-Access VPN, site-to-site VPN, Tunneling to PPP, Security in VPN.MPLS- operation, Routing, Tunneling and use of FEC, Traffic Engineering, MPLS based VPN, overlay networks-P2P connections, USB Tethering, IPv6							
IV	TRAFFIC MODELLING Types of traffic models – need for traffic models – traffic model types - Little's theorem, Need for modeling, Poisson modeling and its failure, Non- poisson models, Network performance evaluation.							
V	Principles certification in many management	on – Access control and: f layers. Infrastructure for	thentication — integrity — key distrib fire walls — attacks and counter measures r network management — The internet IB, SNMP, Security and administration	securitystandardASN.1-	v 1	9		
			T-4-1:			4 =		

CO1: Gain the knowledge of multimedia networking.

Course Outcome CO2: Understand the advanced networking concepts.

CO3: Familiarizes the network security and management.

CO4: Impart the knowledge of advanced network securities.

CO5: Discuss about the network management.

TEXT BOOKS:

- T1. J.F. Kurose & K.W. Ross,"Computer Networking- A top down approach featuring the internet", Pearson, 2nd edition, 2003.
- T2. Walrand .J. Varatya, High performance communication network, Morgan Kauffman Harcourt Asia Pvt. Ltd. 2nd Edition, 2000.

Total instructional hours

45

REFERENCE BOOKS:

- R1. LEOM-GarCIA, WIDJAJA, "Communication networks", TMH seventh reprint 2002.
- R2. Aunurag kumar, D. M Anjunath, Joy kuri, "Communication Networking", Morgan Kaufmann Publishers, 1ed 2004.
- R3. Hersent Gurle & petit, "IP Telephony, packet Pored Multimedia communication Systems", Pearson education 2003.

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PROGRAMME		COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	C
M.E.		16AP2310	INDUSTRIAL AUTOMATION AND CONTROL			0	3
Course Objective 1. Understand principles of switching theory and substance of Study different types of sensors and transducers. 3. Familiarize the architecture of PLC, PLC Ladden installation. 4. Impart knowledge on types of DCS. 5. Understand the basic principles of electric, Hy			nsors and transducers. e of PLC, PLC Ladder diagrams, types of PLCs of DCS.	C and t	their	ems	

Unit	Description	hours	
Ι	SWITCHING THEORY AND SWITCHING ELEMENTS Basic logic gates, Binary elements and variables, logic circuit design. Switching elements: electronic logic gates- relays – pneumatic valves- MPL elements – solenoid valves- interfacing pneumatics and hydraulics.	9	
II	SENSORS AND TRANSDUCERS Binary vs. analog sensors – electric position sensors – pneumatic position sensors – point sensors for variables other than position. Electrical transducers – selection of transducer-final control elements.	9	
III	FLEXIBLE AUTOMATION Programmable logic controllers (PLC) – programming-ladder diagram- PLC communication and networking- PLC selection and installation- examples of PLC applications.	9	
IV	Introduction to DCS- DCS Integrated with PLC and computer system- computer aided measurement and control system- elements and architecture of computer aided measurement and control system- MMI- communication and networking- data transfer techniques- RTO's – computer based data acquisition system (DAQ).	9	
V	APPLICATIONS OF CONTROL SYSTEM Basic Principles of electric, Hydraulic and Pneumatic control systems-Electric oven temperature control-Automatic control of metal width and thickness.		
	Total instructional hours	45	
Cour Outco	CO3: Draw ladder diagrams for given applications	ence system.	

- M.P.Groover, "Automation, Production Systems and Computer Integrated manufacturing", Pearson Education 5th edition, 2009
- T2. David W Pessen, "Industrial Automation Circuit Design and Components", John Wiley & Sons 2011.

REFERENCE BOOKS:

- R1. S.K.Singh, "Industrial Instrumentation and Control", Tata Mc Graw Hill Education Pvt. Ltd. 2012.
 R2. Gary Dunning, "Introduction to Programmable Logic Controllers", Delmar Publisher.
 R3. Webb & Resis, "Programmable Logic Controllers", Prentice Hall of India 2000



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PROGRAMME	COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	C
M.E.	16AP3301	TESTING OF VLSI CIRCUITS	3	0	0 ·	3
Course Objective	 Recall the basics of cor Gain knowledge on tes Learn algorithms for te 	n testing of VLSI circuits. In the string of VLSI circuits. It is of logic circuits. It is of logic circuits. It is of logical circuits. It is of logical circuits. It is of logical circuits.				

Unit	Description	Instructional Hours
I	TESTING AND FAULT MODELLING Introduction to testing – Faults in Digital Circuits – Modelling of faults – Logical Fault Models – Fault detection – Fault Location – Fault dominance – Logic simulation – Types of simulation – Delay models – Gate Level Event – driven simulation.	9
п	TEST GENERATION FOR COMBINATIONAL AND SEQUENTIAL CIRCUITS Test generation for combinational logic circuits – Testable combinational logic circuit design – Test generation for sequential circuits – design of testable sequential circuits.	9
Ш	DESIGN FOR TESTABILITY Design for Testability – Ad-hoc design – Generic scan based design – Classical scan based design – System level DFT approaches.	9
IV	SELF – TEST AND TEST ALGORITHMS Built-In self Test – Test pattern generation for BIST – Circular BIST – BIST Architectures – Testable Memory Design – Test Algorithms – Test generation for Embedded RAMs.	9
V	FAULT DIAGNOSIS Logical Level Diagnosis – Diagnosis by UUT reduction – Fault Diagnosis for Combinational Circuits – Self-checking design – System Level Diagnosis.	9
	Total Instructional Hours	45

CO1: Design models of various fault diagnosis circuits.

Course CO2: Construct test circuit for combinational and sequential processes. Outcome CO3: Analyze the various test generation methods for logic circuits.

CO4: Employ the appropriate design algorithm for constructing logic circuits.

CO5: Suggest suitable circuit for fault diagnosis.

TEXT BOOKS:

- T1. M.Abramovici, M.A.Breuer and A.D. Friedman, "Digital systems and Testable Design", Jaico Publishing House, 2002.
- T2. P.K. Lala, "Digital Circuit Testing and Testability", Academic Press, 2002.

REFERENCE BOOKS:

- R1. M.L.Bushnell and V.D.Agrawal, "Essentials of Electronic Testing for Digital, Memory and Mixed-Signal VLSI Circuits", Kluwer Academic Publishers, 2002.
- R2. A.L.Crouch, "Design Test for Digital IC's and Embedded Core Systems", Prentice Hall International, 2002.

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	L	T	P	C
M.E.	16AP3302	PHOTONICS	3	0	0	3
Course Objective	 Analyze the performa Distinguish the performa Design electronic circ 	ght and its propagation. nce of bistable LASER diodes. mance issues in LASER diodes. tuits for wavelength selection and photo detection. ications for photonic switching.				

Unit	Description	Instructional Hours					
I	INTRODUCTION Function semiconductor laser - Basic concepts of semi conductor laser - Semi conductor quantum wells - Vertical cavity surface emitting lasers - Non linear effects in semiconductor lasers.	9					
П	BISTABLE LASER DIODES Optical Bistability - Bistable switches - Inhomogeneous current injections - absorptive scheme - Dispersive bistable laser diodes - Injection locking - Bistability in laser diode amplifiers - wavelength, power and polarization bistability.						
III	SELF PULSATION & ULTRA SHORT PULSE GENERATORS Self pulsation-theory of self pulsation in laser diodes, Period doubling in modulated laser diodes - Optical chaos - Mode locking in laser diodes - Monolithic mode locked laser diodes. WAVELENGTH SELECTION AND WAVELENGTH SELECTIVE	9					
IV	PHOTODETECTION Wavelength selection - Laser diode amplifier filters - DFB laser diode amplifier - Signal selection, Noise properties and Wavelength selection photo detectors.	9					
V	APPLICATIONS OF PHOTONIC SWITCHING High speed data transmission systems - Clock distribution - All optical fibre communication systems - Clock extraction & dispersion compensation - WDM systems - optical exchange systems - Time division & wavelength division switching - Power mixing & Frequency division switching - Space switches.	9					
	Total Instructional Hours	45					
	CO1: Elaborate the performance issues in various LASERS. CO2: Suggest suitable application for bistable LASER diodes.						

Outcome

CO3: Appraise the solutions for the performance issues in LASER diodes.

CO4: Adapt the suitable circuit for wavelength selection, detection and photo detection.

CO5: Evaluate the applications of photonic switching.

TEXT BOOKS:

- H. Kawaguchi, "Bistabilities and Non-linearities in Laser Diodes", Artech house Inc, Norwood, 1994.
- Saleh, B. E. A., and M. C. Teich., "Fundamentals of Photonics", New York, NY: Wiley, 1991.

REFERENCE BOOKS:

- Sueta and Okoshi, "Fundamental of Ultra fast & Ultra Parallel Opto Electronics", John Wiley & Sons, New R1.
- K. Tada and Hinton. H.S., "Photonic Switching II", Springer Verlag, Berlin, 1990. R2.

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PROGRAMME	COURSE CODE	NAME OF THE COURSE	${f L}$	T	P	C
M.E.	16AP3303	NANO ELECTRONICS	3	0	0	3
Course Objective	 Analyze various prope Understand the import Infer the basics of nan- 	ance of quantum dots in nano structures.				

Unit	Description	Instructional Hours				
I	INTRODUCTION Electronic states in crystal energy bands - 1 D nanostructures (quantum wires) - OD nanostructures (quantum dots) - Concepts of 2 and 3D nanostructures (quantum wells), artificial atomic clusters.	9				
П	FABRICATION AND MEASUREMENT TECHNIQUES Size dependent properties - Size dependent absorption spectra - Blue shift with smaller sizes - Phonons in nanostructures - Contacts at Nano level - AFM (classification) - ISTM tip on a surface.					
III	PROPERTIES Charging of quantum dots - Coulomb blockade - Quantum mechanical treatment of quantum wells - wires and dots - Widening of band gap in quantum dots - Strong and weak confinement - Properties of coupled quantum dots - Optical scattering from Nano defects.	9				
IV	NANO STRUCTURE DEVICES Nano composites – Ceramic - Polymer and metal material composites - Electronic and atomic structure of aggregates and nano particles - Theory and modeling of nano particles fictionalization processes - organic electronics.					
V	Nano systems -Synthesis and characterization methods - Molecular beam epitaxy - MOCVD - chemical routes - nano particles of polymers - pulsed laser deposition - ion beam assisted techniques including embedded nano particles - RF sputteringInert gas condensation.					
	Total Instructional Hours	45				
	CO1: Summarize the concepts on various dimensional nanostructures. CO2: Compile the properties of nanostructure. CO3: Recognize the basics of nanostructure devices and logic devices. CO4: Compile the performance of nano structure devices. CO5: Categories the application circuits of nano structures.					

- T1. K.Bamam and D.Vvedensky "Low Dimensional Semiconductor Structures", Cambridge University Book,
- T2. L.Banyai and S.W.Koch, "Semiconductor Quantum Dots", World Scientific, 1993.

REFERENCE BOOKS:

- J.H. Davies, "An introduction to the physics-a low dimensional semiconductors", Cambridge Press, 1998. Karl Goser, Peter Glosekotter, Jan Dienstuhl., "Nanoelectronics and Nanosystems", Springer, 2004. R1.
- R2.

PR	OGRAMME	CO	OURSE CODE	NAME OF THE COURSE	L	T	P	C
	M.E.		16AP3304	INTERNETWORKING AND MULTIMEDIA	3	0	0	3
Course Objective		1. 2. 3. 4. 5.	Infer the basics of broad Learn the basics of rel	ne requirements of multimedia communicat ad band technology. iable transport protocols. ultimedia communication standards and arc nvolved in data transmission across various	hitectur	res.		
Unit				Description				ructional Hours
Ī	Digital Sound – Evolution of Multimedia C	l, Vide of Inter Coding	rnet Services Model – and Compression for T	c Multimedia Networking – Multimedia Cl Network Requirements for Audio/ Video ext, Image Audio And Video.	aracteri Transfo	istics rm –		9
II	BROADBAND NETWORK TECHNOLOGY Broadband Services – ATM and IP, IPV6, High Speed Switching – Resource Reservation - Buffer							9
III	RELIABLE Multicast ove	TRAN er Sha	NSPORT PROTOCOL red Media Network – 1 rks – Reliable Transport	L AND APPLICATIONS Multicast Routing and Addressing — Scali t Protocols — TCP Adaptation Algorithm —	ng Mul RTP - F	ticast RTCP		9
IV	- MIME - Peer-to-Peer Computing - Shared Application - SIP - SDP. MULTIMEDIA COMMUNICATION STANDARDS Objective of MPEG - 7 Standards - Functionalities and Systems of MPEG-7 MPEG-21 Multimedia Framework Architecture - Content Representation - Content Management and Usage - Intellectual Property Management - Audio Visual System - H264: Guaranteed QOS LAN							9
V	Systems - MPEG_4 Video Transport Across Internet. MULTIMEDIA COMMUNICATION ACROSS NETWORKS Packet Audio/Video in The Network Environment - Video Transport Across Generic Networks - Layered Video Coding- Error Resilient Video Coding Techniques - Scalable Rate Control - Streaming Video Across Internet - Multimedia Transport Across ATM Networks and IP Network - Multimedia Across Wireless Networks.							9
				Total Instruc	tional I	Hours		45
	Course outcome	CO2: 1 CO3: 1 CO4: 0 CO5: 1	Summarize the structure Design a suitable applic Compare and contrast d	rations of multimedia tools and the way in e of broad band techniques and its associate ration using reliable transport protocols. ifferent multimedia standards. r process across various networks.	which the	ney are ards.	; used.	

B. O. Szuprowicz, "Multimedia Networking", McGraw Hill, Newyork, 1995. T1.

K. R. Rao, Zoran S, Bojkovic and Dragorad A, Milovanovic "Multimedia communication systems", PHI, T2.

REFERENCE BOOKS:

Jon Crowcroft, Mark Handley, Ian Wakeman "Internetworking Multimedia" Harcourt, Singapore, 1998. Tay Vaughan, "Multimedia making it to work", 4th edition Tata McGraw Hill, New Delhi, 2000. R1.

R2.

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M.E.		16AP3305	ASIC DESIGN	3	0	0	3
	ourse jective	extraction of ASIC. 4. Learn about different high		ations in ASIC		; circui	it
Unit		Des	scription		Ir	nstruct Hou	
I	Types of ASIO	Cs - Design flow - CMOS trans	IC AND ASIC LIBRARY DESIGN istors CMOS Design rules — Combicell - Transistors as Resistors - Transistors - Transis	inational Logi	c	9	13
П	Capacitance- I PROGRAMM AND program PREP benchm	Logical effort –Library cell design MABLE ASICS, PROGRAMM mable ASIC I/O cells anti fuse	gn - Library architecture. ABLE ASIC LOGIC CELLS - static RAM - EPROM and EEPRON -Altera FLEX - Altera MAX DC &	M technology	_	9	
Ш	PROGRAMM ASIC DESIGN Actel ACT -X Altera FLEX - design languag	MABLE ASIC INTERCONNEC N SOFTWARE AND LOW LE Kilinx LCA - Xilinx EPLD - A -Design systems - Logic Synthe ge - PLA tools -EDIF- CFI design	CT, PROGRAMMABLE EVEL DESIGN ENTRY Litera MAX 5000 and 7000 - Altera esis - Half gate ASIC -Schematic entresis - Response to the control of t	MAX 9000 · ry – Low level	_	9	
IV	Verilog and log	THESIS, SIMULATION AND T gic synthesis -VHDL and logic ulation - Automatic test pattern	synthesis - Types of simulation -Bo	undary scan		9	
V	ASIC CONST. System partition	RUCTION, FLOOR PLANNING - PARTITION - FPGA partitioning - partition	NG, PLACEMENT AND ROUTING ning methods - floor planning - placen - special routing - circuit extraction - I	nent - physical DRC.		9	
	urse (come (device for fabrication. CO2: Conducting research in ASI CO3: Solve design issues and sin	and performance of ASICs and judge IC design.		the b		ited

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PROGRAMME

COURSE CODE

- M.J.S. Smith, "Application Specific Integrated Circuits", Addison Wesley Longman Inc., 1997.
- Farzad Nekoogar and Faranak Nekoogar, "From ASICs to SOCs: A Practical Approach", Prentice Hall PTR, 2003.

- REFERENCE BOOKS:
 R1. Wayne Wolf, "FPGA-Based System Design", Prentice Hall PTR, 2004.
 R2. Rajsuman, "System-on-a-Chip Design and Test", Santa Clara, CA: Artech House Publishers, 2000.
- R3 F. Nekoogar, "Timing Verification of Application-Specific Integrated Circuits (ASICs)", Prentice Hall PTR,

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PROFESSIONAL ELECTIVE VI

PROGRAMME		COURSE CODE	NAME OF THE COURSE	L	T	P	C		
	M.E.	16AP3306	ROBOTICS	3	0	0	3		
Course Objective			vision system.						
Unit			Description				ctional urs		
I	Function, Redecomposition Transformat Algebraic m	assification, Robot Specific toad maps- Topological roat ions, Sensor and sensor p tion matrix and DH transfacthods.	eations, Motion – Bug and tangent algorithm dmaps, Cell decomposition – Trapezoidal and olanning- Kinematics-Forward and Inverse R formation-Inverse Kinematics - Geometric r	d Morse c Cinematics	ell ·	,)		
II	COMPUTER VISION Projection – Optics - Projection on the Image Plane and Radiometry Image Processing – Connectivity - Images-Gray Scale and Binary Images - Blob Filling - Thresholding, Histogram- Convolution - Digital Convolution and Filtering and Masking Techniques- Edge Detection - Mono and Stereo Vision.								
III	SENSORS AND SENSING DEVICES Introduction to various types of sensor- Resistive sensors. Range sensors - LADAR (Laser Distance and Ranging), Sonar, Radar and Infra-red- Introduction to sensing - Light sensing, Heat sensing, touch sensing and Position calculating by using mono-vision camera.								
IV	ARTIFICIAL INTELLIGENCE Uniform Search strategies - Breadth first - Depth first - Depth limited - Iterative and deepening depth first search and Bidirectional search - algorithm- Planning - State-Space Planning Plan-Space Planning - Graph plan/Sat Plan and their Comparison - Multi-agent planning and Multi-agent planning - Probabilistic Reasoning - Bayesian Networks - Decision Trees and Bayes net inference.								
v	Building of	INTEGRATION TO ROBOT Building of 4 axis or 6 axis robot - Vision System for pattern detection - Sensors for obstacle detection - AI algorithms for path finding and decision making.							
			Total Instruct	ional Hou	ırs	4	5		
Course COutcome COutcome			arnt about robotic vision system. Ferential motion and control. ts in various applications.						
TI T1	EXT BOOKS: I. Duda, H		ognition", Wiley-Inter science, 2000.						

- Mallot, "Computational Vision: Information Processing in Perception and Visual Behavior", Cambridge, T2. 2000.

REFERENCE BOOKS:

- R1. Stuart Russell and Peter Norvig, "Artificial Intelligence-A Modern Approach", Pearson Education Series in Artificial Intelligence, 2004.
- Robert Schilling and Craig, "Fundamentals of Robotics: Analysis and Control", Hall of India Private R2. Limited, 2003.
- R3 Forsyth and Ponce, "Computer Vision: A Modern Approach", Person Education, 2003.

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PROC	GRAMME	3 0	COURSE CODE	NAME OF THE COURSE	L	Т	P	C
M.E.			16AP3307	MEMS AND NEMS	3	0	0	3
			10/11/2007					
	urse ective	3. 4.	Infer the fabrication pro Design MEMS sensor.	nd packaging issues in MEMS.				
Unit				Description				Instructional Hours
I	MEMS at	nd N	cations and standards, mi	N s - MEMS processes & features, various icromachining, basic process tools — ep methods — oxidation —evaporation - litho	itaxy – s _l	putterin	ng - ing -	9
II	advanced MATER Silicon - polycrysta	processing	ess tools - sol gel process S FOR MEMS AND ENG on oxide and nitride - The materials - mechanics	s - EFAB. GINEERING ASPECTS in metal films - Polymers - Other mate of Microsystems - static bending -me m - fatigue - and stress and strain - y	erials and chanical	substra vibratio	ates - ons -	9
III	modulus of rigidity - scaling laws in miniaturization. MEMS SENSORS, DESIGN AND PROCESSING Micro sensors (acoustic wave sensors- biomedical sensors- chemical sensors- optical sensors- capacitive sensors- pressure sensors- thermal sensors) - micro actuators (thermal- piezoelectric-electrostatic actuators- micrometers- micro valves & pumps- accelerometer- micro fluidics and							9
IV	devices) - design consideration - process design and mechanical design. MEMS/NEMS SCALING ISSUES AND PACKAGING Introduction - Scaling of physical systems - Mechanical system scaling, Thermal system scaling - Fluidic system scaling - Electrical system scaling - Packaging - mechanical and micro system package - design considerations - Process steps - Die preparation - interconnects - surface and Waser bonding - wire bonding and scaling - 3D packaging and assembly signal Thermal management - Hermetic packaging, Electrical / Micro fluidic / and optical interconnects - Signal mapping transduction - Micro fluidic technology - MEMS and NEMS technology for micro fluidic devices.							
v	Applicati – lab on	ons i chip	- molecular machines -	ealth care – aerospace – industrial productata storage devices – micro reactor – t	ct consum elecomm	er proc unicati	ducts ons -	9
	Servo sys	stems	S.	Total	Instructi	onal F	Iours	45
Outo	urse come FEXT BOC T1. Nad Arte	CO2 CO3 CO4 CO5 OKS dim Mech I	: Summarize MEMS / NE : Analysis the application : Malut and Kirt Williams, " House Inc, Boston, Second	sed for MEMS. MEMS sensors and actuators. EMS scaling issues and packaging. Is of MEMS. An introduction to Micro electro mechar				
1	REFEREN	CE I	BOOKS:					

- Nicolae Lobontiu and Ephrahim Garcia Kluwer, "Mechanics of micro electro mechanical systems", Academic Publishers, Boston, 2001. R1.
- Ivor Brodie and Julius J.Muray, "The Physics of Micro/Nano Fabrication", Springer Science & Business R2.
- Kaoru Ohno, Masatoshi Tanaka, Jun Takeda and Yoshijuki Kawazoe, "Nano and Micromaterials", R3 Springer Science & Business Media, 2008.



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PROGRAMME		COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	\mathbf{C}
M.E.		16AP3308	SYSTEM ON CHIP DESIGN	3	0	0	3
Course Objective	1. 2. 3. 4. 5.	Design combinational and gates. Correlate optimization Study the design princ	various logic gates with minimum size, spacing, an logic functions and analyze delay and testability pro of power in sequential logic machines. iples of FPGA and PLA. anning methods for system design.				nect

Unit	Description	Instructional Hours					
I	LOGIC GATES Introduction- Combinational Logic Functions- Static Complementary Gates- Switch Logic-Alternative Gate Circuits- Low - Power Gates- Delay Through Resistive Interconnect - Delay Through Inductive Interconnect.	9					
П	COMBINATIONAL LOGIC NETWORKS Introduction- Standard Cell - Based Layout- Simulation- Combinational Network Delay- Logic and interconnect Design- Power Optimization- Switch Logic Networks- Combinational Logic Testing.						
III	SEQUENTIAL MACHINES Introduction- Latches and Flip - Flops- Sequential Systems and Clocking Disciplines- Sequential System Design- Power Optimization- Design Validation- Sequential Testing.						
IV	SUBSYSTEM DESIGN Introduction- Subsystem Design Principles- Combinational Shifters- Adders- ALUs- Multipliers- High - Density Memory- Field Programmable Gate Arrays- Programmable Logic Arrays- References- Problems.						
v	FLOOR-PLANNING Introduction - Floor - planning Methods - Block Placement & Channel Definition- Global Routing- switchbox Routing- Power Distribution- Clock Distributions- Floor - planning Tips-Design Validation- Off - Chip Connections - Packages- The I/O Architecture- and PAD Design.						
	Total Instructional Hours	45					
Cours Outco	CO3: Design combinational logic machines with optimism power.	es.					

- Wayne Wolf, "Modern VLSI Design System on Chip Design", Prentice Hall, 3rd Edition, 2008.
- T2. Michael J. Flynn, Wayne Luk, "Computer System Design: System-on-Chip", Wiley Publications, 2003.

REFERENCE BOOKS:

- R1. Michel Robert, Bruno Rouzeyre, Christian Piguet, Marie-Lise Flottes, "SOC Design Methodologies", Springer Science & Business Media, 2001.
- R2.
- Steve Furber, "Arm System-On-Chip Architecture", second edition, Pearson Education India, 2002
 Peter J. Ashenden, Jean Mermet, Ralf Seepold, "System-on-Chip Methodologies & Design Languages", R3 Springer Science & Business Media, 2002.

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PRO	GRAMME	COURSE CODE	NAME OF THE COURSE	\mathbf{L}	T	P	\mathbf{C}
	M.E. 16AP3309		WIRELESS ADHOC AND SENSOR NETWORKS	3	0	0	3
	urse ctive	perspective. 2. Learn different types of M 3. Infer basics of adhoc rout 4. Study the TCP issues in a 5. Learn the architecture and	ting protocols.	design a			tional
I	propagation I (MANETs) as	of Wireless Communication Tec Mechanisms - Characteristics of	chnology – The Electromagnetic Spectrun The Wireless Channel -mobile ad hoc Ns): concepts and architectures. Application Ad hoc and Sensor Networks.	network	S	9	
II	MAC PROTOCOLS FOR AD HOC WIRELESS NETWORKS Issues in designing a MAC Protocol- Classification of MAC Protocols- Contention based protocols- Contention based protocols with Reservation Mechanisms- Contention based protocols with Scheduling Mechanisms – Multi channel MAC-IEEE 802.11						
III	NETWORKS Issues in design Reactive rout	S gning a routing and Transport Lay	PORT LAYER IN AD HOC WI rer protocol for Ad hoc networks- proactiv - Classification of Transport Layer solut	e routing	,	9	į.
IV	WIRELESS SENSOR NETWORKS (WSNS) AND MAC PROTOCOLS Single node architecture: hardware and software components of a sensor node - WSN Network architecture: typical network architectures-data relaying and aggregation strategies -MAC layer Protocols: self-organizing, Hybrid TDMA/FDMA and CSMA based MAC- IEEE 802.15.4.					9	į
V	WSN ROUTING, LOCALIZATION & QOS Issues in WSN routing – OLSR- Localization – Indoor and Sensor Network Localization-absolute and relative localization, triangulation-QOS in WSN-Energy Efficient Design-Synchronization Transport Layer issues.						•
			Total Instruction	al Hour	s	4:	5
	ourse tcome	CO2: Analyze protocols develor CO3: Identify and understand s	n wireless ad hoc and sensor networks. oped for ad hoc and sensor networks. security issues in ad hoc and sensor netword d security issues associated with multicast				

 C.Siva Ram Murthy and B.S.Manoj, "Ad Hoc Wireless Networks – Architectures and Protocols", Pearson Education, 2004.

CO4: Infer the architectures and security issues associated with multicast routing. CO5: Evaluate the QoS related performance measurements of ad hoc and sensor networks.

T2. Carlos De Morais Cordeiro, Dharma Prakash Agrawal, "Ad Hoc and Sensor Networks: Theory and Applications (2nd Edition)", World Scientific Publishing, 2011.

REFERENCE BOOKS:

- R1. Holger Karl, Andreas Willig, "Protocols and Architectures for Wireless Sensor Networks", John Wiley & Sons, Inc., 2005.
- R2. C.K. Toh, "Ad Hoc Mobile Wireless Networks", Pearson Education, 2009.
- R3 Subir Kumar Sarkar, T G Basavaraju, C Puttamadappa, "Ad Hoc Mobile Wireless Networks", Auerbach Publications, 2008.

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PROGRAMME COURSE CODE		URSE CODE	NAME OF THE COURSE		T	P	C		
M.E.		16AP3310	APPLIED MEDICAL IMAGE PROCESSING	3	0	0	3		
Course 2. Objective 3.		2. Discuss a 3. Gather kn medical in 4. Classify t	bout various medical imaging techniques. nowledge on various forms of representation						
Unit		e	Description		Instructional Hours				
I	IMAGE FUNDAMENTALS AND PRE-PROCESSING Image perception- MTF of the visual system- Image fidelity criteria- Image model- Image sampling and quantization – Two dimensional sampling theory-Image quantization- Optimum mean square quantizer- Image transforms – 2D-DFT and other transforms. Image enhancement – point operation- Histogram modeling- spatial operations- Transform operations.								
Π	BASICS OF MEDICAL IMAGE SOURCES Radiology- The electromagnetic spectrum-Computed Tomography - Magnetic Resonance Tomography - ultrasound-nuclear medicine and molecular imaging- radiation protection and dosimetry.								
Ш	Pixels and v representatio formats- Ana - Image qual	MEDICAL IMAGE REPRESENTATION Pixels and voxels – algebraic image operations - gray scale and color representation- depth-colorand look up tables - image file formats- DICOM- other formats- Analyze 7.5 - NifTI and Interfile - Image quality and the signal to noise ratio- MATLAB based simple operations.							
IV	Image segn representatio Shape- Texto Network app	MEDICAL IMAGE ANALYSIS AND CLASSIFICATION Image segmentation- pixel - edge - region based segmentation - Image representation and analysis- Feature extraction and representation- Statistical-Shape- Texture- feature and image classification - Statistical- Rule based- Neural Network approaches.							
V	IMAGE RE Rigid body registration- Image visua based interac	ration-		9					
			Total Instructional	Hours		45			
	Course	CO2: Suggest su	mage processing concepts for medical image itable imaging technique for health complic he suitable form of storing the data.						

Outcome

- T1. Wolfgang Birkfellner, "Applied Medical Image Processing - A Basic course", CRC Press, 2011.
- T2. Atam P.Dhawan, "Medical Image Analysis", Wiley Interscience Publication, NJ, USA 2003.

CO4: Elaborate on various analysis of medical images. CO5: Select suitable method for medical image visualization.

REFERENCE BOOKS:

- R.C.Gonzalez and R.E.Woods, "Digital Image Processing", Second Edition, Pearson Education, 2002. Anil. K. Jain, "Fundamentals of Digital Image Processing", Pearson education, Indian Reprint 2003. R1.
- R2.
- R3 Alfred Horowitz, "MRI Physics for Radiologists - A Visual Approach", Second edition, Springer Verlag Network, 1991.

EEE - HICET

Chairman